

#### Octal T1/E1/J1 Line Interface Unit

#### **Datasheet**

The LXT384 is an octal short haul Pulse Code Modulation (PCM) Line Interface Unit for use in both 1.544 Mbps (T1) and 2.048 Mbps (E1) applications. It incorporates eight independent receivers and eight independent transmitters in a single 144 pin LQFP or 160 ball PBGA package.

The LXT384 transmits shaped waveforms meeting G.703 and T1.102 specifications. The transmit drivers provide low impedance independent of the transmit pattern and supply voltage variations. The LXT384 exceeds the latest transmit return loss specifications, such as ETSI ETS-300166. All transmitters include a power down mode with fast output tristate capability.

The LXT384's differential receiver architecture provides high noise interference margin and is able to work with up to 12 dB of cable attenuation. The optional digital clock recovery PLL and jitter attenuator are referenced to a low frequency 1.544 MHz or 2.048 MHz clock.

The LXT384 incorporates an advanced crystal-less jitter attenuator switchable between the receive and transmit path. The jitter attenuation performance meets the latest international specifications such as CTR12/13. The jitter attenuation performance was optimized for Sychronous Optical NETwork/Sychronous Digital Hierarchy (SONET/SDH) applications.

The LXT384 can be configured as a 7 channel transceiver with G.772 compliant non intrusive protected monitoring points.

The LXT384 includes Hitless Protection Switching (HPS) feature which helps increase quality of service and eliminates relays in redundancy and 1+1 protection applications. Fast tristate-able drivers and a constant delay jitter attenuator are critical to achieving HPS.

### **Product Features**

- Single rail 3.3V supply with 5V tolerant inputs
- Low power consumption of 130mW per channel (typ.)
- Superior crystal-less jitter attenuator
  - Meets ETSI CTR12/13, ITU G.736, G.742, G.823 and AT&T Pub 62411 specifications
  - Optimized for SONET/SDH applications, meets ITU G.783 mapping jitter specification
  - Constant throughput delay jitter attenuator
- Hitless Protection Switching (HPS) for 1 to 1 protection without relays

- Transmit return loss exceeds ETSI ETS 300166
- HDB3, B8ZS, or AMI line encoder/decoder
- Provides protected monitoring points per ITU G.772
- Analog/digital and remote loopback testing functions
- LOS per ITU G.775, ETS 300 233 and T1.231
- 8 bit parallel or 4 wire serial control interface
- Hardware and Software control modes
- JTAG Boundary Scan test port per IEEE 1149.1

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144 pin LQFP and 160 ball PBGA packages



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# **Applications**

- SONET/SDH tributary interfaces
- Digital cross connects
- Public/private switching trunk line interfaces
- Microwave transmission systems
- M13, E1-E3 MUX

Figure 1. LXT384 Detailed Block Diagram

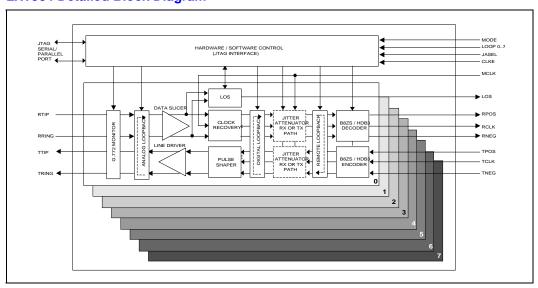
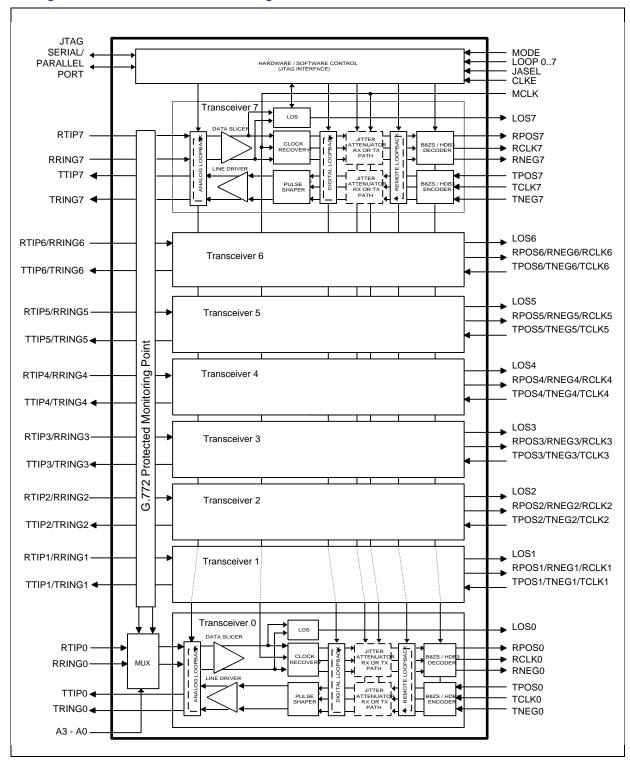




Figure 2. LXT384 Detailed Block Diagram





## 1.0 Pin Assignments and Signal Descriptions

Figure 3. LXT384 Low-Profile Quad Flate Package (LQFP) 144-Pin Assignments and Package Markings

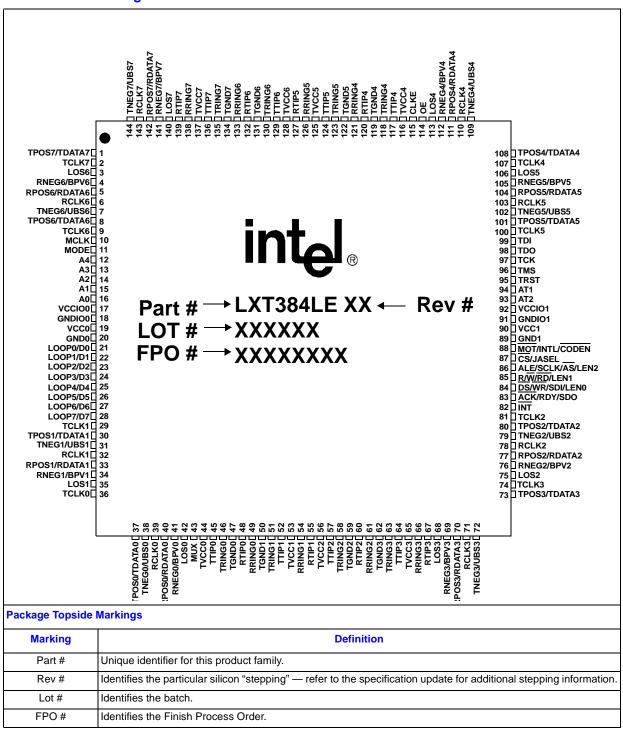




Figure 4. LXT384 Plastic Ball Grid Array (PBGA) Package Pin Assignments

	14	13	12	11	10	9	8	7	6	5	4	3	2	1	
Α	RCLK 4	RPOS 4	RNEG 4	TVCC 4	TRING 4	TGND 4	RTIP 4	RTIP 7	TGND 7	TRING 7	TVCC 7	RNEG 7	RPOS 7	RCLK 7	A
В	TCLK 4	TPOS 4	TNEG 4	TVCC 4	TTIP 4	TGND 4	(RRING 4	RRING 7	TGND 7	TTIP 7	TVCC 7	TNEG 7	TPOS 7	TCLK 7	В
С	RCLK 5	RPOS 5	RNEG 5	TVCC 5	TRING 5	TGND 5	RTIP 5	RTIP 6	TGND 6	TRING 6	TVCC 6	RNEG 6	RPOS 6	RCLK 6	С
D	TCLK 5	TPOS 5	TNEG 5	TVCC 5	TTIP 5	TGND 5	RRING 5	RRING 6	TGND 6	TTIP 6	TVCC 6	TNEG 6	TPOS 6	TCLK 6	D
E	OE	CLKE	LOS 5	LOS 4		-	_	_	_	-	LOS 7	LOS 6	MODE	MCLK	E
F	тск	TDO	TDI	TMS							A 4	$\begin{pmatrix} A \\ 3 \end{pmatrix}$	A 2	A 1	F
G	VCCIO 1	AT 2	TRST	GNDIO 1		1	LXT3	84BE	Ē		GNDIO 0	$\begin{pmatrix} A \\ 0 \end{pmatrix}$	(LOOP)	VCCIO 0	G
н	VCC 1	AT 1	$\overline{\text{MOT}}$	GND 1		(I	вотто	M VIEW	<i>(</i> )		GND 0	(LOOP)	(LOOP 2	(VCC 0	н
J	DS	$R/\overline{W}$	ALE	(CS)							(LOOP)	(LOOP 4	LOOP 5	(LOOP)	J
K	ACK	(INT)	LOS 2	LOS 3							LOS 0	LOS 1	MUX	LOOP 7	ĸ
L	TCLK 2	TPOS 2	TNEG 2	TVCC 2	TTIP 2	TGND 2	RRING 2	(RRING)	TGND 1	TTIP 1	TVCC 1	TNEG 1	TPOS 1	TCLK 1	L
М	RCLK 2	RPOS 2	RNEG 2	TVCC 2	TRING 2	TGND 2	RTIP 2	RTIP 1	TGND 1	TRING 1	TVCC 1	RNEG 1	RPOS 1	RCLK 1	м
N	TCLK 3	TPOS 3	TNEG 3	TVCC 3	TTIP 3	TGND 3	(RRING)	RRING 0	TGND 0	TTIP 0	TVCC 0	TNEG 0	(TPOS 0	TCLK 0	N
Р	RCLK 3	RPOS 3	RNEG 3	TVCC 3	TRING 3	TGND 3	RTIP 3	RTIP 0	TGND 0	TRING 0	TVCC 0	RNEG 0	RPOS 0	RCLK 0	Р
	14	13	12	11	10	9	8	7	6	5	4	3	2	1	



Table 1. LXT384 Pin Description (Sheet 1 of 12)

Pin # QFP	Ball # PBGA	Symbol	<b>I/O</b> <sup>1</sup>	Description				
1	B2	TPOS7	DI	Transmit Positive Data Input.				
1	B2	TDATA7	DI	Transmit Data Input.				
2	B1	TCLK7	DI	Transmit Clock Input. During normal operation TCLK is active, and TPOS and TNEG are sampled on the falling edge of TCLK. If TCLK is Low, the output drivers enter a low power high-Z mode. If TCLK is High for more than 16 clock cycles, the pulse shaping circuit is disabled and the transmit output pulse widths are determined by the TPOS and TNEG duty cycles.  TCLK Operating Mode  Clocked Normal operation  H TAOS (if MCLK supplied)  L Driver outputs enter tri-state  When pulse shaping is disabled, it is possible to overheat and damage the LXT384 device by leaving transmit inputs high continuously. For example a programmable ASIC might leave all outputs high until it is programmed. To prevent this, clock one of these signals: TPOS, TNEG, TCLK or MCLK. Another solution is to set one of these signals low: TPOS, TNEG, TCLK, or OE.  Note: The TAOS generator uses MCLK as a timing reference. In order to assure that the output frequency is within specification limits, MCLK must have the applicable stability.				
3	E3	LOS6	DO	Loss of Signal Output. LOS output is High, indicating a loss of signal, when the incoming signal has no transitions for a specified time interval. The LOS condition is cleared and the output pin returns to Low when the incoming signal has sufficient number of transitions in a specified time interval (details in LOS functional description).				
1. DI:	Digital In	out: DO: Digit	al Outp	ut: DI/O: Digital Bidirectional Port: Al: Analog Input: AO: Analog Output				

DI: Digital Input; DO: Digital Output; DI/O: Digital Bidirectional Port; AI: Analog Input; AO: Analog Output S: Power Supply; N.C.: Not Connected.



Table 1. LXT384 Pin Description (Sheet 2 of 12)

Pin # QFP	Ball # PBGA	Symbol	I/O <sup>1</sup>	Description			
				Receive Negative Data Output.			
				Bipolar Violation Detect Output.			
				Receive Positive Data Output.			
				Receive Data Output			
				Bipolar Mode:			
4	C3	RNEG6	DO	In clock recovery mode, these pins act as active High bipolar non return to zero (NRZ) receive signal outputs. A High signal on RPOS corresponds to receipt of a positive pulse on RTIP/RRING. A High signal on RNEG corresponds to receipt of a negative pulse on RTIP/RRING. These signals are valid on the falling or rising edges of RCLK depending on the CLKE input.			
4 5 5	C3 C2 C2	BPV6 RPOS6	RPOS6	RPOS6	RPOS6	RPOS6 DO	In Data recovery mode, these pins act as RZ data receiver outputs. The output polarity is selectable with CLKE (Active High output polarity when CLKE is High and Active Low Polarity when CLKE is Low).
5	C2	KDATA6	RDATA6 DO	RPOS and RNEG will go to the high impedance state when the MCLK pin is Low.			
				Unipolar Mode:			
				In uni-polar mode, the LXT384 asserts BPV High if any in-service Line Code Violation is detected. RDATA acts as the receive data output.			
				Hardware Mode:			
				During a LOS condition, RPOS and RNEG will remain active.			
				Host Mode:			
				RPOS and RNEG will either remain active or insert AlS into the receive path. Selection is determined by the RAISEN bit in the GCR register.			
				Receive Clock Output.			
				Normal Mode:			
6	6 C1 RCLK	RCLK6	RCLK6 DO	This pin provides the recovered clock from the signal received at RTIP and RRING. Under LOS conditions there is a transition from RCLK signal (derived from the recovered data) to MCLK signal at the RCLK output.			
				Data Recovery Mode:			
			If MCLK is High, the clock recovery circuit is disabled and RPOS and RNEG are internally connected to an EXOR that is fed to the RCLK output for external clock recovery applications.				
				RCLK will be in high impedance state if the MCLK pin is Low.			

DI: Digital Input; DO: Digital Output; DI/O: Digital Bidirectional Port; Al: Analog Input; AO: Analog Output S: Power Supply; N.C.: Not Connected.



Table 1. LXT384 Pin Description (Sheet 3 of 12)

Pin # QFP	Ball # PBGA	Symbol	I/O <sup>1</sup>			Description	
7 7 8 8	D3 D3 D2 D2	TNEG6 UBS6 TPOS6 TDATA6	DI DI DI	transmission of transmission o	Diar Select In itive Data Input.  are active High a positive profice a negative profice of a negative profice	put.  but.  h NRZ inputs. TPOS indicates the ulse whereas TNEG indicates the	TCLK
9	D1	TCLK6	DI	AMI encoding mode) or by the TDATA is the	decoding is done CODEN bit	etermined by the $\overline{\text{CODEN}}$ pin (har in the GCR register (software mod	dware
10	E1	MCLK	DI	Transmit Clock Input.  Master Clock Input. MCLK is an independent, free-running reference clock. It's frequency should be 1.544 MHz for T1 operation and 2.048 MHz for E1 operation.  This reference clock is used to generate several internal reference signals:  • Timing reference for the integrated clock recovery unit  • Timing reference for the integrated digital jitter attenuator  • Generation of RCLK signal during a loss of signal condition  • Reference clock during a blue alarm transmit all ones condition  • Reference timing for the parallel processor wait state generation logic  If MCLK is High, the PLL clock recovery circuit is disabled. In this mode, the LXT384 operates as simple data receiver.  If MCLK is Low, the complete receive path is powered down and the output pins RCLK, RPOS and RNEG are switched to tri-state mode.  MCLK is not required if LXT384 is used as a simple analog front-end without clock recovery and jitter attenuation.  Note: Wait state generation via RDY/ACK is not available if MCLK is			

DI: Digital Input; DO: Digital Output; DI/O: Digital Bidirectional Port; AI: Analog Input; AO: Analog Output S: Power Supply; N.C.: Not Connected.



Table 1. LXT384 Pin Description (Sheet 4 of 12)

Pin # QFP	Ball # PBGA	Symbol	<b>I/O</b> <sup>1</sup>	Description				
11	E2	MODE	DI	LXT384. In Hard and hardwired pile In Parallel Host Monfiguration and In Serial Host mare used.  MODE  Low  High  Vcc/2  For Serial Host Monfiguration and In Serial Host Model I	Dut. This pin is used to select the operating mode of the ware Mode, the parallel processor interface is disabled ins are used to control configuration and report status.  Mode, the parallel port interface pins are used to control direport status.  Dide, the serial interface pins: SDI, SDO, SCLK and CS  Operating Mode  Hardware Mode  Parallel Host Mode  Serial Host Mode  Mode, the pin should connected to a resistive divider 10 kΩ resistors across Vcc and Ground.			
12	F4	A4	DI	Address Select Input. In non-multiplexed host mode, this pin is Address 4 input pin. In hardware mode, this pin must be connected to Ground.				

DI: Digital Input; DO: Digital Output; DI/O: Digital Bidirectional Port; AI: Analog Input; AO: Analog Output S: Power Supply; N.C.: Not Connected.



Table 1. LXT384 Pin Description (Sheet 5 of 12)

Pin # QFP	Ball # PBGA	Symbol	I/O <sup>1</sup>			Des	cription			
13 14 15 16	F3 F2 F1 G3	A3 A2 A1 A0	DI DI DI	intrusive mointernally coroutes the dicircuits. The by activating in order for the and data call If A0, A1, and transceiver with the control of the control	mode, thee mitoring. Durinected to ata from the data on the the remote this operation be observed A2 are L without mode a0 0 0 0 0 1 1 1 0 0 0 0 0 1 1 1 1 1 0 0 0 0 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	se pins are uring proted a specific to see selected e monitor per loopback on to take powed at the Frow, the LX' nitoring cap A1 0 0 1 1 0 0 1 1 0 0 0 1 1 1 0 0 0 1 1 1 0 0 0 1 1 1 0 0 0 1 1 1 0 0 0 1 1 1 0 0 0 1 1 1 0 0 0 1 1 1 0 0 0 1 1 1 1 0 0 0 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	used to section monitoransmit or port to its coport can be for channel lace). In acc RCLKO/RP T384 is colorability.  A0  1  0  1  0  1  0  1  0  1  output 1	elect a specific port for non oring receiver 0 inputs are receive port. Receiver 0 data and clock recovery routed to TTIP0/TRING0 el 0 (TCLK0 must be active ddition, the recovered clock OS0/RNEG0 outputs. Infigured as octal line  Selection  No Protection Monitoring  Receiver 1  Receiver 2  Receiver 3  Receiver 4  Receiver 5  Receiver 6  Receiver 7  No Protection Monitoring  Transmitter 1  Transmitter 1  Transmitter 2  Transmitter 3  Transmitter 4  Transmitter 5  Transmitter 6  Transmitter 7  In the respective channel is		
17	G1	VCCIO0	S	Power (I/O).						
				` '						
18	G4	GNDIO0	S	Ground (I/O).						
19	H1	VCC0	S	Power (Core).						
20	H4	GND0	S	Ground (Co	Ground (Core).					

DI: Digital Input; DO: Digital Output; DI/O: Digital Bidirectional Port; AI: Analog Input; AO: Analog Output S: Power Supply; N.C.: Not Connected.



Table 1. LXT384 Pin Description (Sheet 6 of 12)

Pin # QFP	Ball # PBGA	Symbol	I/O <sup>1</sup>	Description
				Loopback Mode Select/Parallel Data bus Input &Output.
				<u>Host Mode</u>
				When a non-multiplexed microprocessor interface is selected, these pins function as a bi-directional 8-bit data port.
				When a multiplexed microprocessor interface is selected, these pins carry both bi-directional 8-bit data and address inputs A0 -A7.
21	G2	LOOP0/D0	DI/O	In serial Mode, D0-7 should be grounded.
22	H3	LOOP1/D1	DI/O	<u>Hardware Mode</u>
23	H2	LOOP2/D2	DI/O	In hardware mode, the LXT384 works in normal operation if this pin is left open (unconnected).
24	J4	LOOP3/D3	DI/O	The LXT384 enters remote loopback mode, if this pin is Low. In this
25	J3	LOOP4/D4	DI/O	mode, data on TPOS and TNEG is ignored and data received on RTIP and RRING is looped around and retransmitted on TTIP and TRING.
26	J2	LOOP5/D5	DI/O	Note: in data recovery mode, the pulse template cannot be guaranteed
27	J1	LOOP6/D6	DI/O	while in a remote loopback.
28	K1	LOOP7/D7	DI/O	The LXT384 enters analog local loopback mode, if this pin is High. In this mode, data received on RTIP and RRING is ignored and data transmitted on TTIP and TRING is internally looped around and routed back to the receive inputs.
				<b>Note:</b> When these inputs are left open, they stay in a high impedance state. Therefore, the layout design should not route signals with fast transitions near the LOOP pins. This practice will minimize capacitive coupling.
29	L1	TCLK1	DI	Transmit Clock Input.
30	L2	TPOS1	DI	Transmit Positive Data Input.
30	L2	TDATA1	DI	Transmit Data Input.
31	L3	TNEG1	DI	Transmit Negative Data Input.
31	L3	UBS1	DI	Unipolar/Bipolar Select Input.
32	M1	RCLK1	DO	Receive Clock Output.
33	M2	RPOS1	DO	Receive Positive Data Output.
33	M2	RDATA1	DO	Receive Data Output.
34	M3	RNEG1	DO	Receive Negative Data Output.
34	М3	BPV1	DO	Bipolar Violation Detect Output.
35	K3	LOS1	DO	Loss of Signal Output.
36	N1	TCLK0	DI	Transmit Clock Input.
37	N2	TPOS0	DI	Transmit Positive Data Input.
37	N2	TDATA0	DI	Transmit Data Input.
38	N3	TNEG0	DI	Transmit Negative Data Input.
38	N3	UBS0	DI	Unipolar/Bipolar Select Input.
39	P1	RCLK0	DO	Receive Clock Output.
40	P2	RPOS0	DO	Receive Positive Data.
40	P2	RDATA0	DO	Receive Data Output.
41	P3	RNEG0	DO	Receive Negative Data.
41	P3	BPV0	DO	Bipolar Violation Detect.
42	K4	LOS0	DO	Loss of Signal Output.

DI: Digital Input; DO: Digital Output; DI/O: Digital Bidirectional Port; AI: Analog Input; AO: Analog Output S: Power Supply; N.C.: Not Connected.



Table 1. LXT384 Pin Description (Sheet 7 of 12)

Pin # QFP	Ball # PBGA	Symbol	I/O <sup>1</sup>	Description
				Multiplexed/Non-Multiplexed Select Input.
43	K2	MUX	DI	When Low the parallel host interface operates in non-multiplexed mode. When High the parallel host interface operates in multiplexed mode. In hardware mode, tie this unused input low.
44	N4, P4	TVCC0	S	<b>Transmit Driver Power Supply.</b> Power supply pin for the output driver. TVCC pins can be connected to either a 3.3V or 5V power supply. Please refer to the Transmitter description.
				Transmit Tip Output.
				Transmit Ring Output.
45 46	N5 P5	TTIP0 TRING0	AO AO	These pins are differential line driver outputs. TTIP and TRING will be in high impedance state if the TCLK pin is Low or the OE pin is Low. In software mode, TTIP and TRING can be tristated on a port-by-port basis by writing a '1' to the OEx bit in the Output Enable Register (OER).
47	N6, P6	TGND0	S	Transmit Driver Ground. Ground pin for the output driver.
				Receive TIP Input.
48	P7	RTIP0	ΑI	Receive Ring Input.
49	N7	RRING0	AI	These pins are the inputs to the differential line receiver. Data and clock are recovered and output on the RPOS/RNEG and RCLK pins.
50	L6, M6	TGND1	S	Transmit Driver Ground.
51	M5	TRING1	AO	Transmit Ring Output.
52	L5	TTIP1	AO	Transmit Tip Output.
53	L4, M4	TVCC1	S	Transmit Driver Power Supply.
54	L7	RRING1	Al	Receive Ring Input.
55	M7	RTIP1	Al	Receive Tip Input.
56	L11, M11	TVCC2	S	Transmit Driver Power Supply.
57	L10	TTIP2	AO	Transmit Tip Output.
58	M10	TRING2	AO	Transmit Ring Output.
59	L9, M9	TGND2	S	Transmit Driver Ground.
60	M8	RTIP2	Al	Receive TIP Input.
61	L8	RRING2	ΑI	Receive Ring Input.
62	N9, P9	TGND3	S	Transmit Driver Ground.
63	P10	TRING3	AO	Transmit Ring.
64	N10	TTIP3	AO	Transmit Tip Output.
65	N11, P11	TVCC3	S	Transmit Driver Power Supply.
66	N8	RRING3	Al	Receive Ring Input.
67	P8	RTIP3	AI	Receive Tip Input.
68	K11	LOS3	DO	Loss of Signal Output.
4 5	Distriction	- 1 DO D'-''	-10-1-	ut. DI/O: Digital Bidiractional Borts Al. Analog Innut. AO: Analog Output

DI: Digital Input; DO: Digital Output; DI/O: Digital Bidirectional Port; AI: Analog Input; AO: Analog Output S: Power Supply; N.C.: Not Connected.



Table 1. LXT384 Pin Description (Sheet 8 of 12)

Pin # QFP	Ball # PBGA	Symbol	I/O <sup>1</sup>	Description	
69	P12	RNEG3	DO	Receive Negative Data Output.	
69	P12	BPV3	DO	Bipolar Violation Detect Output.	
70	P13	RPOS3	DO	Receive Positive Data Output.	
70	P13	RDATA3	DO	Receive Data Output.	
71	P14	RCLK3	DO	Receive Clock Output.	
72	N12	TNEG3	DI	Transmit Negative Data Input.	
72	N12	UBS3	DI	Unipolar/Bipolar Select Input.	
73	N13	TPOS3	DI	Transmit Positive Data Input.	
73	N13	TDATA3	DI	Transmit Data Input.	
74	N14	TCLK3	DI	Transmit Clock Input.	
75	K12	LOS2	DO	Loss of Signal Output.	
76	M12	RNEG2	DO	Receive Negative Data Output.	
76	M12	BPV2	DO	Bipolar Violation Detect Output.	
77	M13	RPOS2	DO	Receive Positive Data Output.	
77	M13	RDATA2	DO	Receive Data Output.	
78	M14	RCLK2	DO	Receive Clock Output.	
79	L12	TNEG2	DI	Transmit Negative Data Input.	
79	L12	UBS2	DI	Unipolar/Bipolar Select Input.	
80	L13	TPOS2	DI	Transmit Positive Data Input.	
80	L13	TDATA2	DI	Transmit Data Input.	
81	L14	TCLK2	DI	Transmit Clock Input.	
82	K13	ĪNT	OD	Interrupt. This active Low, maskable, open drain output requires an external 10k pull up resistor. If the corresponding interrupt enable bit is enabled, INT goes Low to flag the host when the LXT384 changes state (see details in the interrupt handling section). The microprocessor INT input should be set to level triggering.	
				Data Transfer Acknowledge Output (Motorola Mode).	
				Ready Output (Intel mode).	
				Serial Data Output (Serial Mode).	
				Motorola Mode	
83 83	K14 K14	ACK RDY	DO DO	A Low signal during a data bus read operation indicates that the information is valid. A Low signal during a write operation acknowledges that a data transfer into the addressed register has been accepted (acknowledge signal). Wait states only occur if a write cycle immediately follows a previous read or write cycle (e.g. read modify write).	
83	K14	SDO	DO	Intel Mode	
				A High signal acknowledges that a register access operation has been completed. (Ready Signal) A Low signal on this pin signals that a data transfer operation is in progress. The pin goes tristate after completion of a bus cycle.  Serial Mode	
				If CLKE is High, SDO is valid on the rising edge of SCLK. If CLKE is Low, SDO is valid on the falling edge of SCLK. This pin goes into High Z state during a serial port write access.	

DI: Digital Input; DO: Digital Output; DI/O: Digital Bidirectional Port; AI: Analog Input; AO: Analog Output S: Power Supply; N.C.: Not Connected.



Table 1. LXT384 Pin Description (Sheet 9 of 12)

Pin # QFP	Ball # PBGA	Symbol	I/O <sup>1</sup>	Description			
				Data Strobe Input (Motorola Mode).			
				Write Enable Input (Intel mode).			
				Serial Data Input (Serial Mode).			
84	J14	DS	DI	Line Length Equalizer Input (Hardware Mode).			
84	J14	WR	DI	Host Mode			
84 84	J14 J14	SDI LEN0	DI DI	This pin acts as data strobe in Motorola mode and as Write Enable in Intel mode. In serial mode, this pin is used as Serial Data Input.			
				Hardware Mode			
				This pin determines the shape and amplitude of the transmit pulse. Please refer to Table 2.			
				Read/Write Input (Motorola Mode).			
				Read Enable Input (Intel Mode).			
		_		Line Length Equalizer Input (Hardware Mode).			
85	J13	R/W	DI	Host Mode			
85 85	J13 J13	RD LEN1	DI DI	This pin functions as the read/write signal in Motorola mode and as the Read Enable in Intel mode.			
				Hardware Mode			
				This pin determines the shape and amplitude of the transmit pulse. Please refer to Table 2.			
				Address Latch Enable Input.			
				Shift Clock Input (Serial Mode).			
				Address Strobe (Motorola Mode).			
00	140	A.I. E.	-	Line Length Equalizer Input (Hardware Mode).			
86	J12	ALE	DI	Host Mode			
86 86	J12 J12	SCLK AS	DI DI	The address on the multiplexed address/data bus is clocked into the device with the falling edge of ALE.			
86	J12	LEN2	DI	In serial Host mode, this pin acts as serial shift clock.			
				In Motorola mode, this pin acts a active Low address strobe.			
				Hardware Mode			
				This pin determines the shape and amplitude of the transmit pulse. Please refer to Table 2.			
				Chip Select/Jitter Attenuator Select Input. Host Mode			
				This active Low input is used to access the serial/parallel interface. For each read or write operation, $\overline{CS}$ must transition from High to Low, and remain Low.			
				Hardware Mode			
87	J11	CS	DI	This input determines the Jitter Attenuator position:			
87	J11	JASEL		JASEL JA Position			
				L Transmit Path			
				H Receive Path			
				Z Disabled			

DI: Digital Input; DO: Digital Output; DI/O: Digital Bidirectional Port; AI: Analog Input; AO: Analog Output S: Power Supply; N.C.: Not Connected.



Table 1. LXT384 Pin Description (Sheet 10 of 12)

Pin # QFP	Ball # PBGA	Symbol	I/O <sup>1</sup>	Description	
88	H12	MOT/INTL/ CODEN	DI	Motorola/Intel/Codec Enable Select Input.  Host Mode: When Low, the host interface is configured for Motorola microcontrollers. When High, the host interface is configured for Intel microcontrollers.  Hardware Mode: Determines the line encode/decode selection when in unipolar mode. When Low, B8ZS/HDB3 encoders/decoders are enabled for T1/E1 respectively. When High, enables AMI encoder/decoder (transparent mode).	
89	H11	GND1	S	Ground (Core).	
90	H14	VCC1	S	Power (Core).	
91	G11	GNDIO1	S	Ground (I/O).	
92	G14	VCCIO1	S	Power (I/O).	
93	G13	AT2	AO	JTAG Analog Output Test Port 2.	
94	H13	AT1	Al	JTAG Analog Input Test Port 1.	
95	G12	TRST		JTAG Controller Reset Input. Input is used to reset the JTAG controller. TRST is pulled up internally and may be left disconnected.	
96	F11	TMS	DI	JTAG Test Mode Select Input. Used to control the test logic state machine. Sampled on rising edge of TCK. TMS is pulled up internally and may be left disconnected.	
97	F14	TCK	DI	JTAG Clock Input. Clock input for JTAG. Connect to GND when not used.	
98	F13	TDO	DO	JTAG Data Output. Test Data Output for JTAG. Used for reading all serial configuration and test data from internal test logic. Updated on falling edge of TCK.	
99	F12	TDI	DI	JTAG Data Input. Test Data input for JTAG. Used for loading serial instructions and data into internal test logic. Sampled on rising edge of TCK. TDI is pulled up internally and may be left disconnected.	
100	D14	TCLK5	DI	Transmit Clock Input.	
101	D13	TPOS5	DI	Transmit Positive Data Input.	
101	D13	TDATA5	DI	Transmit Data Input.	
102	D12	TNEG5	DI	Transmit Negative Data Input.	
102	D12	UBS5	DI	Unipolar/Bipolar Select Input.	
103	C14	RCLK5	DO	Receive Clock Output.	
104	C13	RPOS5	DO	Receive Positive Data Output.	
104	C13	RDATA5	DO	Receive Data Output.	
105 105	C12 C12	RNEG5 BPV5	DO DO	Receive Negative Data Output.	
				Bipolar Violation Detect Output.	
106	E12	LOS5	DO	Loss of Signal Output.	
107	B14	TCLK4	DI	Transmit Clock Input.	

<sup>1.</sup> DI: Digital Input; DO: Digital Output; DI/O: Digital Bidirectional Port; AI: Analog Input; AO: Analog Output S: Power Supply; N.C.: Not Connected.



Table 1. LXT384 Pin Description (Sheet 11 of 12)

Pin # QFP	Ball # PBGA	Symbol	<b>1/0</b> <sup>1</sup>	Description		
108	B13	TPOS4	DI	Transmit Positive Data Input.		
108	B13	TDATA4	DI	Transmit Data Input.		
109	B12	TNEG4	DI	Transmit Negative Data Input.		
109	B12	UBS4	DI	Unipolar/Bipolar Select Input.		
110	A14	RCLK4	DO	Receive Clock Output.		
111	A13	RPOS4	DO	Receive Positive Data Output.		
111	A13	RDATA4	DO	Receive Data Output.		
112	A12	RNEG4	DO	Receive Negative Data Output.		
112	A12	BPV4	DO	Bipolar Violation Detect Output.		
113	E11	LOS4	DO	Loss of Signal Output.		
114	E14	OE	DI	Output Driver Enable Input. If this pin is asserted Low all analog driver outputs immediately enter a high impedance mode to support redundancy applications without external mechanical relays. All other internal circuitry stays active. In software mode, TTIP and TRING can be tristated on a port-by-port basis by writing a '1' to the OEx bit in the Output Enable Register (OER).		
115	E13	CLKE	DI	Clock Edge Select Input. In clock recovery mode, setting CLKE High causes RDATA or RPOS and RNEG to be valid on the falling edge of RCLK and SDO to be valid on the rising edge of SCLK. Setting CLKE Low makes RDATA or RPOS and RNEG to be valid on the rising edge of RCLK and SDO to be valid on the falling edge of SCLK. In Data recovery Mode, RDATA or RPOS/RNEG are active High output polarity when CLKE is High and active Low polarity when CLKE is Low.		
				CLKE RPOS/RNEG SDO		
				L RCLK SCLK		
				H RCLK SCLK		
116	A11, B11	TVCC4	S	Transmit Driver Power Supply.		
117	B10	TTIP4	AO	Transmit Tip Output.		
118	A10	TRING4	AO	Transmit Ring Output.		
119	A9, B9	TGND4	S	Transmit Driver Ground.		
120	A8	RTIP4	ΑI	Receive Tip Input.		
121	B8	RRING4	ΑI	Receive Ring Input.		
122	C9, D9	TGND5	S	Transmit Driver Ground.		
123	C10	TRING5	AO	Transmit Ring Output.		
124	D10	TTIP5	AO	Transmit Tip Output.		
125	C11, D11	TVCC5	S	Transmit Driver Power Supply.		
126	D8	RRING5	Al	Receive Ring Input.		
127	C8	RTIP5	Al	Receive Tip Input.		
128	C4, D4	TVCC6	S	Transmit Driver Power Supply.		
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DI: Digital Input; DO: Digital Output; DI/O: Digital Bidirectional Port; AI: Analog Input; AO: Analog Output S: Power Supply; N.C.: Not Connected.



Table 1. LXT384 Pin Description (Sheet 12 of 12)

Pin # QFP	Ball # PBGA	Symbol	I/O <sup>1</sup>	Description		
129	D5	TTIP6	AO	Transmit Tip Output.		
130	C5	TRING6	AO	Transmit Ring Output.		
131	C6, D6	TGND6	S	Transmit Driver Ground.		
132	C7	RTIP6	Al	Receive Tip Input.		
133	D7	RRING6	Al	Receive Ring Input.		
134	A6, B6	TGND7	S	Transmit Driver Ground.		
135	A5	TRING7	AO	Transmit Ring Output.		
136	B5	TTIP7	AO	Transmit Tip Output.		
137	A4, B4	TVCC7	S	Transmit Driver Power Supply.		
138	B7	RRING7	Al	Receive Ring Input.		
139	A7	RTIP7	Al	Receive Tip Input.		
140	E4	LOS7	DO	Loss of Signal Output.		
141	А3	RNEG7	DO	Receive Negative Data Output.		
141	А3	BPV7	DO	Bipolar Violation Detect Output.		
142	A2	RPOS7	DO	Receive Positive Data Output.		
142	A2	RDATA7	DO	Receive Data Output.		
143	A1	RCLK7	DO	Receive Clock Output.		
144	В3	TNEG7	DI	Transmit Negative Data Input.		
144	В3	UBS7	DI	Unipolar/Bipolar Select Input.		
4 DI	A. Di. District Languit DO. District Outside District Dis					

DI: Digital Input; DO: Digital Output; DI/O: Digital Bidirectional Port; AI: Analog Input; AO: Analog Output S: Power Supply; N.C.: Not Connected.

### 2.0 Functional Description

Figure 1 is a block diagram of the LXT384. The LXT384 is a fully integrated octal line interface unit designed for T1 1.544 Mbps and E1 2.048 Mbps short haul applications.

Each transceiver front end interfaces with four lines, one pair for transmit, one pair for receive. These two lines comprise a digital data loop for full duplex transmission.

The LXT384 can be controlled through hard-wired pins or by a microprocessor through a serial or parallel interface (Host mode).

The transmitter timing reference is TCLK, and the receiver reference clock is MCLK. The LXT384 is designed to operate without any reference clock when used as an analog front-end (line driver and data recovery). MCLK is mandatory if the on chip clock recovery capability is used. All eight clock recovery circuits share the same reference clock defined by the MCLK input signal.

#### 2.1 Initialization

During power up, the transceiver remains static until the power supply reaches approximately 60% of VCC. During power-up, an internal reset sets all registers to their default values and resets the status and state machines for the LOS.



#### 2.1.1 Reset Operation

Writing to the reset register (RES) initiates a 1 microsecond reset cycle, except in Intel non-multiplexed mode. In Intel non-multiplexed mode, the reset cycle takes 2 microseconds. Please refer to Host mode section for more information. This operation sets all LXT384 registers to their default values.

#### 2.2 Receiver

The eight receivers in the LXT384 are identical. The following paragraphs describe the operation of one.

The twisted-pair input is received via a 1:2 step down transformer. Positive pulses are received at RTIP, negative pulses at RRING. Recovered data is output at RPOS and RNEG in the bipolar mode and at RDATA in the unipolar mode. The recovered clock is output at RCLK. RPOS/RNEG validation relative to RCLK is pin selectable (CLKE).

The receive signal is processed through the peak detector and data slicers. The peak detector samples the received signal and determines its maximum value. A percentage of the peak value is provided to the data slicers as a threshold level to ensure optimum signal-to-noise ratio. For DSX-1 applications (line length inputs LEN2-0 from 011 to 111) the threshold is set to 70% (typical) of the peak value. This threshold is maintained above the specified level for up to 15 successive zeros over the range of specified operating conditions. For E1 applications (LEN2-0 = 000), the threshold is 50% (typical).

The receiver is capable of accurately recovering signals with up to 12 dB of attenuation (from 2.4 V), corresponding to a received signal level of approximately 500 mV. Maximum line length is 1500 feet of ABAM cable (approximately 6 dB of attenuation). Regardless of received signal level, the peak detectors are held above a minimum level of 0.150 V (typical) to provide immunity from impulsive noise.

After processing through the data slicers, the received signal goes to the data and timing recovery section. The data and timing recovery circuits provide an input jitter tolerance better than required by Pub 62411 and ITU G.823, as shown in Test Specifications, Figure 33.

Depending on the options selected, recovered clock and data signals may be routed through the jitter attenuator, through the B8ZS/HDB3/AMI decoder, and may be output to the framer as either bipolar or unipolar data.

#### 2.2.1 Loss of Signal Detector

The loss of signal detector in the LXT384 uses a dedicated analog and digital loss of signal detection circuit. It is independent of its internal data slicer comparators and complies to the latest ITU G.775 and ANSI T1.231 recommendations. Under software control, the detector can be configured to comply to the ETSI ETS 300 233 specification (LACS Register). In hardware mode, the LXT384 supports LOS per G.775 for E1 and ANSI T1.231 for T1 operation.

The receiver monitor loads a digital counter at the RCLK frequency. The counter is incremented each time a zero is received, and reset to zero each time a one (mark) is received. Depending on the operation mode, a certain number of consecutive zeros sets the LOS signal. The recovered clock is replaced by MCLK at the RCLK output with a minimum amount of phase errors. MCLK is



required for receive operation. When the LOS condition is cleared, the LOS flag is reset and another transition replaces MCLK with the recovered clock at RCLK. RPOS/RNEG will reflect the data content at the receiver input during the entire LOS detection period for that channel.

#### 2.2.1.1 E1 Mode

In G.775 mode, a loss of signal is detected if the signal is below 200mV typ. for 32 consecutive pulse intervals. When the received signal reaches 12.5% ones density (4 marks in a sliding 32-bit period) with no more than 15 consecutive zeros and the signal level exceeds 250mV typ., the LOS flag is reset and another transition replaces MCLK with the recovered clock at RCLK.

In ETSI 300 233 mode, a loss of signal is detected if the signal is below 200mV for 2048 consecutive intervals (1 ms). The LOS condition is cleared and the output pin returns to Low when the incoming signal has transitions when the signal level is equal or greater than 250mV for more than 32 consecutive pulse intervals.

#### 2.2.1.2 T1 Mode

The T1.231 LOS detection criteria is employed. LOS is detected if the signal is below 200mV for 175 contiguous pulse positions. The LOS condition is terminated upon detecting an average pulse density of 12.5% over a period of 175 contiguous pulse positions starting with the receipt of a pulse. The incoming signal is considered to have transitions when the signal level is equal or greater than 250mV.

#### 2.2.1.3 Data Recovery Mode

In data recovery mode, the LOS digital timing is derived from a internal self timed circuit. RPOS/RNEG stay active during loss of signal. The analog LOS detector complies with ITU-G.775 recommendation. The LXT384 monitors the incoming signal amplitude. Any signal below 200mV for more than 30 $\mu$ s (typical) will assert the corresponding LOS pin. The LOS condition is cleared when the signal amplitude rises above 250mV. The LXT384 requires more than 10 and less than 255 bit periods to declare a LOS condition in accordance to ITU G.775.

#### 2.2.2 Alarm Indication Signal (AIS) Detection

The AIS detection is performed by the receiver independent of any loopback mode. This feature is available in host mode only with clock recovery. Because there is no clock in data recovery mode, AIS detection will not work in that mode. AIS requires MCLK to have clock applied, since this function depends on the clock to count the number of ones in an interval.

#### 2.2.2.1 E1 Mode

Two different detection modes are available depending on the LACS register setting:

• ETSI ETS300233 Mode

The AIS condition is declared when the received data stream contains less than 3 zeros within a period of 512 bits.

The AIS condition is cleared when 3 or more zeros within 512 bits are detected.

• ITU G.775 Mode

The AIS condition is declared when, within two consecutive 512 bit periods, less than 3 zeros are detected for each 512 bit period.



The AIS condition is cleared when, within two consecutive 512 bit periods, 3 or more zeros are detected for each 512 bit period.

#### 2.2.2.2 T1 Mode

ANSI T1.231 detection is employed.

The AIS condition is declared when less than 9 zeros are detected in any string of 8192 bits. This corresponds to a 99.9% ones density over a period of 5.3ms.

The AIS condition is cleared when the received signal contains 9 or more zeros in any string of 8192 bits.

#### 2.2.3 Receive Alarm Indication Signal (RAIS)

The receiver will generate all ones to RPOS and RNEG outputs upon LOS, when bit 6, RAISEN, for Receive Alarm Indication Signal Enable, is set in the Global Control Register, GCR. This can affect the AIS status by setting to one if the signal at RTIP and RRING is all zeroes, or be clearing to zero if the signal at RTIP and RRING is all ones. Because of this, mask the AIS interrupt enable bits before setting or resetting RAISEN. This will prevent inadvertent interrupts during programming.

#### 2.2.4 In Service Code Violation Monitoring

In unipolar I/O mode with HDB3/B8ZS decoding, the LXT384 reports bipolar violations on RNEG/BPV for one RCLK period for every HDB3/B8ZS code violation that is not part of the zero code substitution rules. In AMI mode, all bipolar violations (two consecutive pulses with the same polarity) are reported at the BPV output.

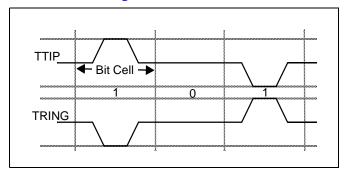
#### 2.3 Transmitter

The eight low power transmitters of the LXT384 are identical. Transmit data is clocked serially into the device at TPOS/TNEG in the bipolar mode or at TDATA in the unipolar mode. The transmit clock (TCLK) supplies the input synchronization. Unipolar I/O and HDB3/B8ZS/AMI encoding/decoding is selected by pulling TNEG High for more than 16 consecutive TCLK clock cycles. The transmitter samples TPOS/TNEG or TDATA inputs on the falling edge of TCLK. Refer to the Test Specifications Section for MCLK and TCLK timing characteristics. If TCLK is not supplied, the transmitter remains powered down and the TTIP/TRING outputs are held in a High Z state. In addition, fast output tristatability is also available through the OE pin (all ports) and/or the port's  $\overline{\text{OEx}}$  bit in the Output Enable Register (OER).

Zero suppression is available only in Unipolar Mode. The two zero-suppression types are B8ZS, used in T1 environments, and HDB3, used in E1 environments. The scheme selected depends on whether the device is set for T1 or E1 operation (determined by LEN2-0 pulse shaping settings). The LXT384 also supports AMI line coding/decoding as shown in Figure 5. In Hardware mode, AMI coding/decoding is selected by the  $\overline{\text{CODEN}}$  pin. In host mode, AMI coding/decoding is selected by bit 4 in the GCR (Global Control Register).



Figure 5. 50% AMI Encoding



Each output driver is supplied by a separate power supply (TVCC and TGND). The transmit pulse shaper is bypassed if no MCLK is supplied while TCLK is pulled High. In this case TPOS and TNEG control the pulse width and polarity on TTIP and TRING. With MCLK supplied and TCLK pulled High, the driver enters TAOS (Transmit All Ones pattern). Note: the TAOS generator uses MCLK as a timing reference. In order to assure that the output frequency is within specification limits, MCLK must have the applicable stability. TAOS is inhibited during Remote Loopback.

### 2.3.1 Transmit Pulse Shaping

The transmitted pulse shape is internally generated using a high speed D/A converter. Shaped pulses are further applied to the line driver for transmission onto the line at TTIP and TRING. The line driver provides a constant low output impedance regardless of whether it is driving marks, spaces or if it is in transition. This well controlled dynamic impedance provides excellent return loss when used with external precision resistors (± 1% accuracy) in series with the transformer.

#### 2.3.1.1 Hardware Mode

In hardware mode, pins LEN0-2 determine the pulse shaping as described in Table 2. The LEN settings also determine whether the operating mode is T1 or E1.

**Note:** In hardware mode, all eight ports will share the same pulse shaping setting. Independent pulse shaping for each channel is available in host mode.

#### **2.3.1.2** Host Mode

In Host Mode, the contents of the Pulse Shaping Data Register (PSDAT) determines the shape of pulse output at TTIP/TRING. Please refer to Table 24 and Table 25.



LEN2	LEN1	LEN0	Line Length <sup>1</sup>	Cable Loss <sup>2</sup>	Operation Mode			
0	1	1	0 - 133 ft. ABAM	0.6 dB				
1	0	0	133 - 266 ft. ABAM	1.2 dB				
1	0	1	266 - 399 ft. ABAM	1.8 dB	T1			
1	1	0	399 - 533 ft. ABAM	2.4 dB				
1	1	1	533 - 655 ft. ABAM	3.0 dB				
0	0	0	E1 G.703, 75 $\Omega$ coaxial cable and 120 $\Omega$ twisted pair cable.					
1. Line	Line length from LXT384 to DSX-1 cross-connect point.							

Table 2. Line Length Equalizer Inputs

#### 2.3.1.3 Output Driver Power Supply

The output driver power supply (TVCC pins) can be either 3.3V or 5V nominal. When TVCC=5V, LXT384 drives both E1 (75 $\Omega$ /120 $\Omega$ ) and T1 100 $\Omega$  lines through a 1:2 transformer and 11 $\Omega$ /9.1 $\Omega$  series resistors.

When TVCC=3.3V, the LXT384 drives E1 (75 $\Omega$ /120 $\Omega$ ) lines through a 1:2 transformer and 11 $\Omega$  series resistor. A configuration with a 1:2 transformer and without series resistors should be used to drive T1 100 $\Omega$  lines.

The Channel 4 (TVCC4) power supply pin is used to determine 3.3V or 5.0V transmit operation.

Removing the series resistors for T1 applications with TVCC=3.3V, improves the power consumption of the device. See Table 36.

On the other hand, series resistors in the transmit configuration improve the transmit return loss performance. Good transmit return loss performance minimizes reflections in harsh cable environments. In addition, series resistors provide protection against surges coupled to the device. The resistors should be used in systems requiring protection switching without external relays. Please refer to Figure 6 for the recommended external line circuitry.

### 2.3.1.4 Power Sequencing

For the LXT384, we recommend sequencing TVCC first then VCC second or at the same time as TVCC to prevent excessive current draw.

#### 2.4 Driver Failure Monitor

The LXT384 transceiver incorporates an internal power Driver Failure Monitor (DFM) in parallel with TTIP and TRING that is capable of detecting secondary shorts without cable. DFM is available only in configurations with no transmit series resistors (T1 mode with TVCC=3.3V). This feature is available in the serial and parallel host modes but not available in the hardware mode of operation.

A capacitor, charged via a measure of the driver output current and discharged by a measure of the maximum allowable current, is used to detect a secondary short failure. Secondary shorted lines draw excess current, overcharging the cap. When the capacitor charge deviates outside the nominal

<sup>2.</sup> Maximum cable loss at 772KHz.

#### LXT384 — Octal T1/E1/J1 Transceiver



charge window, a driver short circuit fail (DFM) is reported in the respective register by setting an interrupt. During a long string of spaces, a short-induced overcharge eventually bleeds off, clearing the DFM flag.

Note: unterminated lines of adequate length ( $\lambda/4$ ) may effectively behave as short-circuits as seen by the driver and therefore trigger the DFM. Under these circumstances, the alarm should be disabled.

In addition, LXT384 features output driver short-circuit protection. When the output current exceeds 100 mA, LXT384 limits the driver's output voltage to avoid damage.



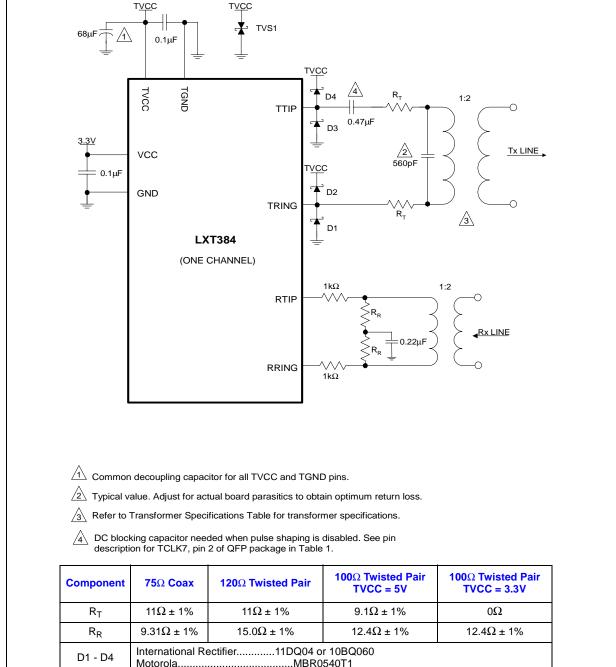


Figure 6. External Transmit/Receive Line Circuitry

Component	<b>75</b> Ω <b>Coa</b> x	120Ω Twisted Pair	100Ω Twisted Pair TVCC = 5V	100Ω Twisted Pair TVCC = 3.3V		
R <sub>T</sub>	11Ω ± 1%	11Ω ± 1%	9.1Ω ± 1%	Ω0		
R <sub>R</sub>	9.31Ω ± 1%	15.0Ω ± 1%	12.4Ω ± 1%	12.4Ω ± 1%		
D1 - D4	International Rectifier11DQ04 or 10BQ060 MotorolaMBR0540T1					
TVS1	SGS-ThomsonSMLVT 3V3 3.3V Transient Voltage Suppressor (TVCC=3.3V SemtechSMCJ5.0AC 5.0V Transient Voltage Suppressor (TVCC=5.0V Transient Voltage Suppresso					



#### 2.5 Line Protection

Figure 6 on page 29 shows recommended line interface circuitry. In the receive side, the 1 k $\Omega$  series resistors protect the receiver against current surges coupled into the device. Due to the high receiver impedance (70 k $\Omega$  typ.) the resistors do not affect the receiver sensitivity. In the transmit side, the Schottky diodes D1-D4 protect the output driver. While not mandatory for normal operation, these protection elements are strongly recommended to improve the design robustness.

#### 2.6 Jitter Attenuation

A digital Jitter Attenuation Loop (JAL) combined with a FIFO provides Jitter attenuation. The JAL is internal and requires no external crystal nor high-frequency (higher than line rate) reference clock.

In Host Mode, the Global Control Register (GCR) determines whether the JAL is positioned in the receive or transmit path. In Hardware Mode, the JAL position is determined by the JASEL pin.

The FIFO is a 32 x 2-bit or 64 x 2-bit register (selected by the FIFO64 bit in the GCR). Data is clocked into the FIFO with the associated clock signal (TCLK or RCLK), and clocked out of the FIFO with the dejittered JAL clock (Figure 7). When the FIFO is within two bits of overflowing or underflowing, the FIFO adjusts the output clock by 1/8 of a bit period. The Jitter Attenuator produces a constant delay of 16 or 32 bits in the associated path (refer to test specifications). This feature can be used for hitless switching applications. This advanced digital jitter attenuator meets latest jitter attenuation specifications. See Table 3.

Under software control, the low limit jitter attenuator corner frequency depends on FIFO length and the JACF bit setting (this bit is in the GCR register). In Hardware Mode, the FIFO length is fixed to 64 bits. The corner frequency is fixed to 6 Hz for T1 mode and 3.5 Hz for E1 mode.

**Table 3. Jitter Attenuation Specifications** 

T1	<b>E</b> 1		
AT&T Pub 62411	ITU-T G.736		
GR-253-CORE <sup>1</sup>	ITU-T G.742 <sup>3</sup>		
	ITU-T G.783 <sup>4</sup>		
TR-TSY-000009 <sup>2</sup>	ETSI CTR12/13		
	BAPT 220		

- 1. Category I, R5-203.
- 2. Section 4.6.3.
- 3. Section 6.2 When used with the SXT6234 E2-E1 mux/demux.
- 4. Section 6.2.3.3 combined jitter when used with the SXT6251 21E1 mapper.



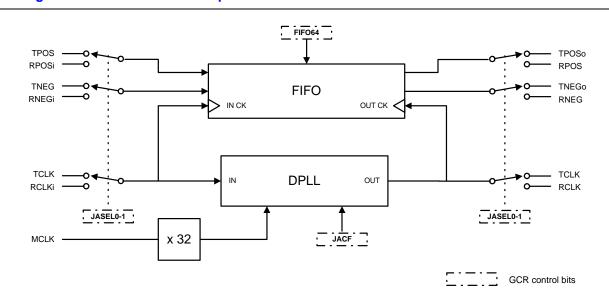


Figure 7. Jitter Attenuator Loop

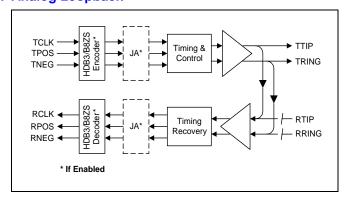
### 2.7 Loopbacks

The LXT384 offers three loopback modes for diagnostic purposes. In hardware mode, the loopback mode is selected with the LOOPn pins. In software mode, the ALOOP, DLOOP and RLOOP registers are employed.

### 2.7.1 Analog Loopback

When selected, the transmitter outputs (TTIP & TRING) are connected internally to the receiver inputs (RTIP & RRING) as shown in Figure 8. Data and clock are output at RCLK, RPOS & RNEG pins for the corresponding transceiver. Note: signals on the RTIP & RRING pins are ignored during analog loopback.

Figure 8. Analog Loopback

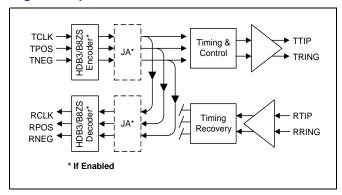




#### 2.7.2 Digital Loopback

The digital loopback function is available in software mode only. When selected, the transmit clock and data inputs (TCLK, TPOS & TNEG) are looped back and output on the RCLK, RPOS & RNEG pins (see Figure 9). The data presented on TCLK, TPOS & TNEG is also output on the TTIP & TRING pins. Note: signals on the RTIP & RRING pins are ignored during digital loopback.

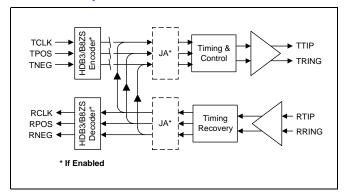
Figure 9. Digital Loopback



### 2.7.3 Remote Loopback

During remote loopback (see Figure 10), the RCLK, RPOS & RNEG outputs routed to the transmit circuits and output on the TTIP & TRING pins. Note: input signals on the TCLK, TPOS & TNEG pins are ignored during remote loopback.

Figure 10. Remote Loopback



**Note:** In data recovery mode, the pulse template cannot be guaranteed while in a remote loopback.

#### 2.7.4 Transmit All Ones (TAOS)

In Hardware mode, the TAOS mode is set by pulling TCLK High for more than 16 MCLK cycles. In software mode, TAOS mode is set by asserting the corresponding bit in the TAOS Register. In addition, automatic ATS insertion (in case of LOS) may be set using the ATS Register. Note: the TAOS generator uses MCLK as a timing reference, therefore TAOS doesn't work in data recovery mode. In order to assure that the output frequency is within specification limits, MCLK must have the applicable stability. DLOOP does not function when TAOS is active.



Figure 11. TAOS Data Path

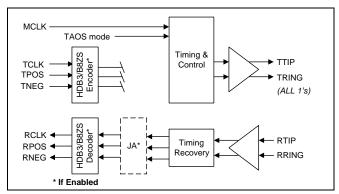


Figure 12. TAOS with Digital Loopback

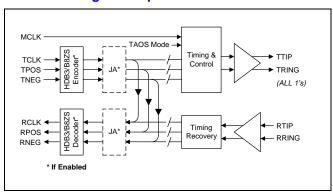
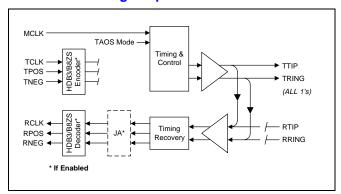


Figure 13. TAOS with Analog Loopback



### 2.8 G.772 Performance Monitoring

The LXT384 can be configured as an octal line interface unit with all channels working as regular transceivers. In applications using only seven channels, the eighth channel can be configured to monitor any of the remaining channels inputs or outputs. The monitoring is non-intrusive per ITU-T G.772. Figure 1 on page 7 illustrates this concept.



The monitored line signal (input or output) goes through channel 0 clock and data recovery. The signal can be observed digitally at the RCLK/RPOS/RNEG outputs. This feature can also be used to create timing interfaces derived from a E1 signal. Channel 0 also displays the appropriate LOS state for the monitored channel, both in transmit and receive directions.

In addition, channel 0 can be configured to a Remote Loopback while in monitoring mode (TCLK0 must be active in order for this operation to take place). This will output the same data as in the signal being monitored at the channel 0 output (TTIP/TRING). The output signal can then be connected to a standard test equipment with an E1 electrical interface for monitoring purposes (non -intrusive monitoring).

### 2.9 Hitless Protection Switching (HPS)

The LXT384 transceivers include an output driver tristatability feature for T1/E1 redundancy applications. This feature greatly reduces the cost of implementing redundancy protection by eliminating external relays. Please refer to Application Note 119 for guidelines for implementing redundancy systems for both T1 and E1 operation using the LXT380/1/4/6/8.

### 2.10 Operation Mode Summary

Table 4 lists summarizes all the LXT384 hardware settings and corresponding operating modes.

**Table 4. Operation Mode Summary** 

MCLK	TCLK	LOOP <sup>1</sup>	Receive Mode	Transmit Mode	Loopback
Clocked	Clocked	Open	Data/Clock recovery	Pulse Shaping ON	No Loopback
Clocked	Clocked	L	Data/Clock recovery	Pulse Shaping ON	Remote Loopback
Clocked	Clocked	Н	Data/Clock recovery	Pulse Shaping ON	Analog Loopback
Clocked	L	Open	Data/Clock recovery	Power down	No Loopback
Clocked	L	L	Data/Clock Recovery	Power down	No effect on op.
Clocked	L	Н	Data/Clock Recovery	Power down	No Analog Loopback
Clocked	Н	Open	Data/Clock Recovery	Transmit All Ones	No Loopback
Clocked	Н	L	Data/Clock Recovery	Pulse Shaping ON	Remote Loopback
Clocked	Н	Н	Data/Clock Recovery	Transmit All Ones	No effect on op.
L	Clocked	Open	Power Down	Pulse Shaping ON	No Loopback
L	Clocked	L	Power Down	Pulse Shaping ON	No Remote Loopback
L	Clocked	Н	Power Down	Pulse Shaping ON	No effect on op.
L	Н	Open	Power Down	Pulse Shaping OFF	No Loopback
L	Н	L	Power Down	Pulse Shaping OFF	No Remote Loop
L	Н	Н	Power Down	Pulse Shaping OFF	No effect on op.
L	L	Х	Power Down	Power down	No Loopback
Н	Clocked	Open	Data Recovery	Pulse Shaping ON	No Loopback
Н	Clocked	L	Data Recovery	Data Recovery Pulse Shaping OFF Remote Loopback	
1. Hardw	are mode o	nly.			



MCLK	TCLK	LOOP <sup>1</sup>	Receive Mode	Transmit Mode	Loopback
Н	Clocked	Н	Data Recovery	Pulse Shaping ON	Analog Loopback
Н	L	Open	Data Recovery	Power down	No Loopback
Н	L	L	Data Recovery	Pulse Shaping OFF	Remote Loopback
Н	Н	Open	Data Recovery	Pulse Shaping OFF	No Loopback
Н	Н	L	Data Recovery	Pulse Shaping OFF	Remote Loopback
Н	Н	Н	Data Recovery	Pulse Shaping OFF	Analog Loopback
1. Hardw	1. Hardware mode only.				

Table 4. Operation Mode Summary (Continued)

### 2.11 Interfacing with 5V Logic

The LXT384 can interface directly with 5V TTL family devices. The internal input pads are tolerant to 5V outputs from TTL and CMOS family devices.

#### 2.12 Parallel Host Interface

The LXT384 incorporates a highly flexible 8-bit parallel microprocessor interface. The interface is generic and is designed to support both non-multiplexed and multiplexed address/data bus systems for Motorola and Intel bus topologies. Two pins (MUX and MOT/INTL) select four different operating modes as shown in Table 5.

Table 5. Microprocessor Interface Selection

	Pin	Operating Mode
MUX	MOT/INTL	Operating mode
Low	Low	Motorola, Non-Multiplexed
Low	High	Intel, Non-Multiplexed
High	Low	Motorola, Multiplexed
High	High	Intel, Multiplexed

The interface includes an address bus (A4 - A0) and a data bus (D7 - D0) for non-multiplexed operation and an 8-bit address/data bus for multiplexed operation.  $\overline{WR}$ ,  $\overline{RD}$ ,  $R/\overline{W}$ ,  $\overline{CS}$ , ALE,  $\overline{DS}$ ,  $\overline{INT}$  and  $RDY/\overline{ACK}$  are used as control signals. A significant enhancement is an internal wait-state generator that controls an Intel and Motorola compatible handshake output signal  $(RDY/\overline{ACK})$ . In Motorola mode,  $\overline{ACK}$  Low signals valid information is on the data bus. During a write cycle a Low signal acknowledges the acceptance of the write data.

In Intel mode, RDY High signals to the controlling processor that the bus cycle can be completed. While Low the microprocessor must insert wait states. This allows the LXT384 to interface with wait-state capable microcontrollers, independent of the processor bus speed. To activate this function a reference clock is required on the MCLK pin.

There is one exception to write cycle timing for Intel non-multiplexed mode: Register 0Ah, the reset register. Because of timing issues, the RDY line remains high after the first part of the cycle is done, not signalling write cycle completion with another transition low. Add 2 microseconds of



delay to allow the reset cycle to completely initialize the device before proceeding. The overall duration of the Reset cycle from CS low to Reset cycle completion is 3 microseconds when using Intel non-multiplexed host mode.

An additional active Low interrupt output signal indicates alarm conditions like LOS and DFM to the microprocessor.

The LXT384 has a 5-bit address bus and provides 22 user accessible 8-bit registers for configuration, alarm monitoring and control of the chip.

#### 2.12.1 Motorola Interface

The Motorola interface is selected by asserting the  $\overline{MOT}/INTL$  pin Low. In non-multiplexed mode, the falling edge of  $\overline{DS}$  is used to latch the address information on the address bus. In multiplexed operation the address on the multiplexed address data bus is latched into the device with the falling edge of  $\overline{AS}$ . In non-multiplexed mode,  $\overline{AS}$  should be pulled High.

The  $R/\overline{W}$  signal indicates the direction of the data transfer. The  $\overline{DS}$  signal is the timing reference for all data transfers and typically has a duty cycle of 50%. A read cycle is indicated by asserting  $R/\overline{W}$  High with a falling edge on  $\overline{DS}$ . A write cycle is indicated by asserting  $R/\overline{W}$  Low with a rising edge on  $\overline{DS}$ .

Both cycles require the  $\overline{CS}$  signal to be Low and the Address pins to be actively driven by the microprocessor. Note:  $\overline{CS}$  and  $\overline{DS}$  can be connected together in Motorola mode. In a write cycle, the data bus is driven by the microprocessor. In a read cycle, the bus is driven by the LXT384.

#### 2.12.2 Intel Interface

The Intel interface is selected by asserting the  $\overline{MOT}/INTL$  pin High. The LXT384 supports non-multiplexed interfaces with separate address and data pins when MUX is asserted Low, and multiplexed interfaces when MUX is asserted High. The address is latched in on the falling edge of ALE. In non-multiplexed mode, ALE should be pulled High.  $R/\overline{W}$  is used as the  $\overline{RD}$  signal and  $\overline{DS}$  is used as the  $\overline{WR}$  signal. A read cycle is indicated to the LXT384 when the processor asserts  $\overline{RD}$  Low while the  $\overline{WR}$  signal is held High. A write operation is indicated to the LXT384 by asserting  $\overline{WR}$  Low while the  $\overline{RD}$  signal is held High. Both cycles require the  $\overline{CS}$  signal to be Low.

### 2.13 Interrupt Handling

#### 2.13.1 Interrupt Sources

There are three interrupt sources:

- Status change in the LOS (Loss of Signal) status register (04H). The LXT384 analog/digital loss of signal processor continuously monitors the receiver signal and updates the specific LOS status bit to indicate presence or absence of a LOS condition.
- Status change in the DFM (Driver Failure Monitoring) status register (05H). The LXT384 smart power driver circuit continuously monitors the output drivers signal and updates the specific DFM status bit to indicate presence or absence of a secondary driver short circuit condition.
- Status change in the AIS (Alarm Indication Signal) status register (13H). The LXT384 receiver monitors the incoming data stream and updates the specific AIS status bit to indicate presence or absence of a AIS condition.



## 2.13.2 Interrupt Enable

The LXT384 provides a latched interrupt output ( $\overline{\text{INT}}$ ). An interrupt occurs any time there is a transition on any enabled bit in the status register. Registers 06H, 07H and 14H are the LOS, DFM and AIS interrupt enable registers (respectively). Writing a logic "1" into the mask register will enable the respective bit in the respective Interrupt status register to generate an interrupt. The power-on default value is all zeroes. The setting of the interrupt enable bit does not affect the operation of the status registers.

Registers 08H, 09H and 15H are the LOS, DFM and AIS (respectively) interrupt status registers. When there is a transition on any enabled bit in a status register, the associated bit of the interrupt status register is set and an interrupt is generated (if one is not already pending). When an interrupt occurs, the  $\overline{\text{INT}}$  pin is asserted Low. The output stage of the  $\overline{\text{INT}}$  pin consists only of a pull-down device; an external pull-up resistor of approximately 10k ohm is required to support wired-OR operation.

## 2.13.3 Interrupt Clear

When an interrupt occurs, the interrupt service routine (ISR) should read the *interrupt status* registers (08H, 09H and 15H) to identify the interrupt source. Reading the Interrupt Status register clears the "sticky" bit set by the interrupt. Automatically clearing the register prepares it for the next interrupt.

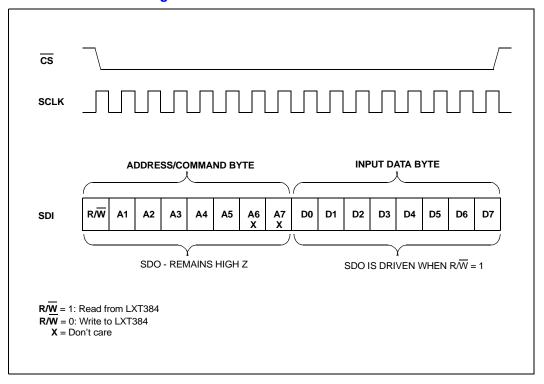
The ISR should then read the corresponding *status monitor register* to obtain the current status of the device. Note: there are three status monitor registers: the LOS (04H), the DFM (05H) and the AIS (013H). Reading either status monitors register will clear its corresponding interrupts on the rising edge of the read or data strobe. When all pending interrupts are cleared, the INT pin goes High.

#### 2.14 Serial Host Mode

The LXT384 operates in Serial Host Mode when the MODE pin is tied to VCCIO÷2. Figure 14 shows the SIO data structure. The registers are accessible through a 16 bit word: an 8bit Command/Address byte (bits  $R/\overline{W}$  and A1-A7) and a subsequent 8bit data byte (bits D0-7). Bit  $R/\overline{W}$  determines whether a read or a write operation occurs. Bits A5-0 in the Command/Address byte address specific registers (the address decoder ignores bits A7-6). The data byte depends on both the value of bit  $R/\overline{W}$  and the address of the register as set in the Command/Address byte.



Figure 14. Serial Host Mode Timing



# 3.0 Register Descriptions

Table 6. Serial and Parallel Port Register Addresses (Sheet 1 of 2)

		Add	Address		
Name	Symbol	Serial Port A7-A1	Parallel Port A7-A0	Mode	
ID Register	ID	xx00000	xxx00000	R	
Analog Loopback	ALOOP	xx00001	xxx00001	R/W	
Remote Loopback	RLOOP	xx00010	xxx00010	R/W	
TAOS Enable	TAOS	xx00011	xxx00011	R/W	
LOS Status Monitor	LOS	xx00100	xxx00100	R	
DFM Status Monitor	DFM	xx00101	xxx00101	R	
LOS Interrupt Enable	LIE	xx00110	xxx00110	R/W	
DFM Interrupt Enable	DIE	xx00111	xxx00111	R/W	
LOS Interrupt Status	LIS	xx01000	xxx01000	R	
DFM Interrupt Status	DIS	xx01001	xxx01001	R	
Software Reset Register	RES	xx01010	xxx01010	R/W	
Performance Monitoring	MON	xx01011	xxx01011	R/W	



Table 6. Serial and Parallel Port Register Addresses (Sheet 2 of 2)

		Add		
Name	Symbol	Serial Port A7-A1	Parallel Port A7-A0	Mode
Digital Loopback	DL	xx01100	xxx01100	R/W
LOS/AIS Criteria Selection	LOSC	xx01101	xxx01101	R/W
Automatic TAOS Select	ATS	xx01110	xxx01110	R/W
Global Control Register	GCR	xx01111	xxx01111	R/W
Pulse Shaping Indirect Address Register	PSIAD	xx10000	xxx10000	R/W
Pulse Shaping Data Register	PSDAT	xx10001	xxx10001	R/W
Output Enable Register	OER	xx10010	xxx10010	R/W
AIS Status Register	AIS	xx10011	xxx10011	R
AIS Interrupt Enable	AISIE	xx10100	xxx10100	R/W
AIS Interrupt Status	AISIS	xx10101	xxx10101	R

Table 7. Register Bit Names (Sheet 1 of 2)

Regist	Register			Bit								
Name	Sym	RW	7	6	5	4	3	2	1	0		
ID Register	ID	R	ID7	ID6	ID5	ID4	ID3	ID2	ID1	ID0		
Analog Loopback	ALOOP	R/W	AL7	AL6	AL5	AL4	AL3	AL2	AL1	AL0		
Remote Loopback	RLOOP	R/W	RL7	RL6	RL5	RL4	RL3	RL2	RL1	RL0		
TAOS Enable	TAOS	R/W	TAOS7	TAOS6	TAOS5	TAOS4	TAOS3	TAOS2	TAOS1	TAOS0		
LOS Status Monitor	LOS	R	LOS7	LOS6	LOS5	LOS4	LOS3	LOS2	LOS1	LOS0		
DFM Status Monitor	DFM	R	DFM7	DFM6	DFM5	DFM4	DFM3	DFM2	DFM1	DFM0		
LOS Interrupt Enable	LIE	R/W	LIE7	LIE6	LIE5	LIE4	LIE3	LIE2	LIE1	LIE0		
DFM Interrupt Enable	DIE	R/W	DIE7	DIE6	DIE5	DIE4	DIE3	DIE2	DIE1	DIE0		
LOS Interrupt Status	LIS	R	LIS7	LIS6	LIS5	LIS4	LIS3	LIS2	LIS1	LIS0		
DFM Interrupt Status	DIS	R	DIS7	DIS6	DIS5	DIS4	DIS3	DIS2	DIS1	DIS0		
Software Reset Register	RES	R/W	RES7	RES6	RES5	RES4	RES3	RES2	RES1	RES0		
Performance Monitoring	MON	R/W	Reserved	Reserved	Reserved	Reserved	А3	A2	A1	A0		
Digital Loopback	DL	R/W	DL7	DL6	DL5	DL4	DL3	DL2	DL1	DL0		
LOS/AIS Criteria Select	LACS	R/W	LACS7	LACS6	LACS5	LACS4	LACS3	LACS2	LACS1	LACS0		
Automatic TAOS Select	ATS	R/W	ATS7	ATS6	ATS5	ATS4	ATS3	ATS2	ATS1	ATS0		



## Table 7. Register Bit Names (Sheet 2 of 2)

Register			Bit								
Name	Sym	RW	7	6	5	4	3	2	1	0	
Global Control Register	GCR	R/W	Reserved	RAISEN	CDIS	CODEN	FIFO64	JACF	JASEL1	JASEL0	
Pulse Shaping Indirect Address Register	PSIAD	R/W	Reserved	Reserved	Reserved	Reserved	Reserved	LENAD2	LENAD1	LENAD0	
Pulse Shaping Data Register	PSDAT	R/W	Reserved	Reserved	Reserved	Reserved	Reserved	LEN2	LEN1	LEN0	
Output Enable Register	OER	R/W	ŌE7	OE6	OE5	ŌE4	ŌE3	ŌE2	OE1	ŌE0	
AIS Status Register	AIS	R	AIS7	AIS6	AIS5	AIS4	AIS3	AIS2	AIS1	AIS0	
AIS Interrupt Enable	AISIE	R/W	AISIE7	AISIE6	AISIE5	AISIE4	AISIE3	AISIE2	AISIE1	AISIE0	
AIS Interrupt Status	AISIS	R	AISIS7	AISIS6	AISIS5	AISIS4	AISIS3	AISIS2	AISIS1	AISIS0	

# Table 8. ID Register, ID (00h)

Bit	Name	Function
7-0	ID7-ID0	This register contains a unique revision code and is mask programmed.  For Rev. A4, 00h  For Rev. A5, 15h

# Table 9. Analog Loopback Register, ALOOP (01h)

Bit	Name	Function
7-0	AL7-AL0	Setting a bit to "1" enables analog local loopback for transceivers 7- 0 respectively.

## Table 10. Remote Loopback Register, RLOOP (02h)

Bit	Name	Function
7-0	RL7-RL0	Setting a bit to "1" enables remote loopback for transceivers 7-0 respectively.

# Table 11. TAOS Enable Register, TAOS (03h)

Bit <sup>1</sup>	Name	Function <sup>2</sup>
7-0	TAOS7-TAOS0	Setting a bit to "1" causes a continuous stream of marks to be sent out at the TTIP and TRING pins of the respective transceiver 7-0.

1. On power up all register bits are set to "0".

<sup>2.</sup> MCLK is used as timing reference. If MCLK is not available then the channel TCLK is used as the reference. This feature is not available in data recovery and line driver mode (MCLK= High and TCLK = High).



## Table 12. LOS Status Monitor Register, LOS (04h)

Bit <sup>1</sup>	Name	Function
7-0	LOS7-LOS0	Respective bit(s) are set to "1" every time the LOS processor detects a valid loss of signal condition in transceivers 7-0.

<sup>1.</sup> On power up all register bits are set to "0". Any change in the state causes an interrupt. All LOS interrupts are cleared by a single read operation.

## Table 13. DFM Status Monitor Register, DFM (05h)

Bit	Name	Function <sup>1</sup>		
7-0	DFM7-DFM0	Respective bit(s) are set to "1" every time the short circuit monitor detects a valid secondary output driver short circuit condition in transceivers 7-0. Note: DFM is available only in configurations with no transmit series resistors (T1 mode with TVCC=3.3V).		
1. 0	1. On power-up all the register bits are set to "0". All DFM interrupts are cleared by a single read operation.			

## Table 14. LOS Interrupt Enable Register, LIE (06h)

Bit	Name	Function <sup>1</sup>			
7-0	LIE7-LIE0	Transceiver 7-0 LOS interrupts are enabled by writing a "1" to the respective bit.			
1. 0	On power-up all the register bits are set to "0" and all interrupts are disabled.				

## Table 15. DFM Interrupt Enable Register, DIE (07h)

Bit	Name	Function <sup>1</sup>			
7-0	DIE7-DIE0	Transceiver 7-0 DFM interrupts are enabled by writing a "1" to the respective bit.			
1. O	On power-up all the register bits are set to "0" and all interrupts are disabled.				

## Table 16. LOS Interrupt Status Register, LIS (08h)

Bit	Name	Function <sup>1</sup>			
7-0	LIS7-LIS0	These bits are set to "1" every time a LOS status change has occurred since the last cleared interrupt in transceivers 7-0 respectively.			
1. 0	1. On power up all register bits are set to "0".				

## Table 17. DFM Interrupt Status Register, DIS (09h)

Bit	Name	Function <sup>1</sup>				
7-0	DIS7-DIS0	These bits are set to "1" every time a DFM status change has occurred since the last cleared interrupt in transceivers 7-0 respectively.				
1. 0	1. On power up all register bits are set to "0".					



## Table 18. Software Reset Register, RES (0Ah)

Bit	Name	Function
7-0	RES7-RES0	Writing to this register initiates a 1 microsecond reset cycle, except in Intel non-multiplexed mode. This operation sets all LXT384 registers to their default values. When using Intel non-multiplexed host mode, extend cycle time to 2 microseconds. Please refer to Host Mode section for details.

## Table 19. Performance Monitoring Register, MON (0Bh)

Bit	Name	Function
3-0	A3:A0	Protected Monitoring selection. See Table 1, page 15.
4-7	reserved	Reserved.

## Table 20. Digital Loopback Register, DL (0Ch)

Bit <sup>1</sup>	Name	Function <sup>2</sup>
7-0	DL7-DL0	Setting a bit to "1" enables digital loopback for the respective transceiver.

<sup>1.</sup> On power up all register bits are set to "0".

## Table 21. LOS/AIS Criteria Register, LCS (0Dh)

Bit <sup>1</sup>	Name	Function <sup>2</sup>			
7-0	LCS7-LCS0	T1 Mode  Don't care. T1.231 compliant LOS/AIS detection is used.  E1 Mode  Setting a bit to "1" selects the ETSI 300233 LOS. Setting a bit to "0" selects G.775 LOS mode. AIS works correctly for both ETSI and ITU when the bit is cleared to "0". See errata 10.3 or higher for a way to implement ETSI LOS and AIS.			
1. On power-on reset the register is set to "0".					

## Table 22. Automatic TAOS Select Register, ATS (0Eh)

7-0 A	TS7-ATS0	Setting a bit to "1" enables automatic TAOS generation whenever a LOS condition is detected in the respective transceiver.

<sup>1.</sup> On power-on reset the register is set to "0".

<sup>2.</sup> During digital loopback LOS and TAOS stay active and independent of TCLK, while data received on TPOS/TNEG/CKLK is looped back to RPOS/RNEG/RCLK.

<sup>2.</sup> T1 or E1 operation mode is determined by the PSDAT settings.

<sup>2.</sup> This feature is not available in data recovery and line driver mode (MCLK= High and TCLK = High).



Table 23. Global Control Register, GCR (0Fh)

Bit <sup>1</sup>	Name	Function					
0	JASEL0	These bits determine the jitter attenuator position:					
		JASEL0	JASEL1	JA Position			
1	JASFI 1	1	0	Transmit Path			
'	JASELI	1	1	Receive Path			
		0	х	Disabled			
2	JACF		This bit determines the jitter attenuator low limit 3dB corner frequency. Refer to the Jitter Attenuator specifications for details. See Table 42 on page 59.				
3	FIFO64	This bit determing 0 = 32 bit 1 = 64 bit	· ·- ·-				
4	CODEN	This bit selects the zero suppression code for unipolar operation mode:  0 = B8ZS/HDB3 (T1/E1 respectively)  1 = AMI					
	CDIS	This bit controls	enables/disable	s the short circuit protection	feature:		
5		0 = enabled 1 = disabled					
		This bit controls	automatic AIS i	nsertion in the receive path v	when LOS occurs:		
6	RAISEN	0 = Receive AIS insertion disabled on LOS 1 = RPOS/RNEG = AIS on LOS					
				e in data recovery mode (MC t value to prevent inadverten			
7	-	- Reserved.					
1. 0	1. On power-on reset the register is set to "0".						

Table 24. Pulse Shaping Indirect Address Register, PSIAD (10h)

Bit <sup>1</sup>	Name	Function					
	LENAD 0-2	The three bit value written to these bits determine the channel to be addressed. Data can be read from (written to) the Pulse Shaping Data Register (PSDAT).					
		LENAD 0-2	Channel	<b>LENAD 0-2</b>	<u>Channel</u>		
0-2		0h	0	4h	4		
		1h	1	5h	5		
		2h	2	6h	6		
		3h	3	7h	7		
3 - 7	-	Reserved.					
1. 0	1. On power-on reset the register is set to "0".						



Table 25. Pulse Shaping Data Register, PSDAT (11h)

Bit	Name		Function					
	LEN 0-2 <sup>1, 3</sup>	LEN0-2 determine the LXT384 operation mode: T1 or E1. In addition, for T1 operation, LEN2-0 set the pulse shaping to meet the T1.102 pulse template at the DSX-1 cross-connect point for various cable lengths:						
		LEN2	LEN1	LEN0	Line Length	Cable Loss <sup>2</sup>	Operation Mode	
0-2		0	1	1	0 - 133 ft. ABAM	0.6 dB		
0-2		1	0	0	133 - 266 ft. ABAM	1.2 dB		
		1	0	1	266 - 399 ft. ABAM	1.8 dB	T1	
		1	1	0	399 - 533 ft. ABAM	2.4 dB		
		1	1	1	533 - 655 ft. ABAM	3.0 dB		
		0	0	0	E1 G.703, 75Ω coax twisted pair cable.	ial cable and 120 $\Omega$	E1	
3 - 7	-	Reserve	ed.					

<sup>1.</sup> On power-on reset the register is set to "0".

## Table 26. Output Enable Register, OER (12h)

Bit <sup>1</sup>	Name	Function				
7-0	OE7 - OE0	Setting a bit to "1" tristates the output driver of the corresponding transceiver.				
1. C	1. On power-up all the register bits are set to "0".					

## Table 27. AIS Status Monitor Register, AIS (13h)

Bit <sup>1</sup>	Name	Function				
7-0	AIS7-AIS0	Respective bit(s) are set to "1" every time the receiver detects a AIS condition in transceivers 7-0.				
1. 0	1. On power-up all the register bits are set to "0". All AIS interrupts are cleared by a single read operation.					

# Table 28. AIS Interrupt Enable Register, AISIE (14h)

Bit <sup>1</sup>	Name	Function					
7-0	AISIE7-AISIE0	Transceiver 7-0 AIS interrupts are enabled by writing a "1" to the respective bit.					
1. O	1. On power-up all the register bits are set to "0".						

<sup>2.</sup> Maximum cable loss at 772 KHz.

When reading LEN, bit values appear inverted. "B2" revision silicon will fix this so the bits read back correctly.



#### Table 29. AIS Interrupt Status Register, AISIS (15h)

Bit <sup>1</sup>	Name	Function			
7-0	AISIS7-AISIS0	These bits are set to "1" every time a AIS status change has occurred since the last clear interrupt in transceivers 7-0 respectively.			
1. O	1. On power-up all the register bits are set to "0".				

# 4.0 JTAG Boundary Scan

## 4.1 Overview

The LXT384 supports IEEE 1149.1 compliant JTAG boundary scan. Boundary scan allows easy access to the interface pins for board testing purposes.

In addition to the traditional IEE1149.1 digital boundary scan capabilities, the LXT384 also includes analog test port capabilities. This feature provides access to the TIP and RING signals in each channel (transmit and receive). This way, the signal path integrity across the primary winding of each coupling transformer can be tested.

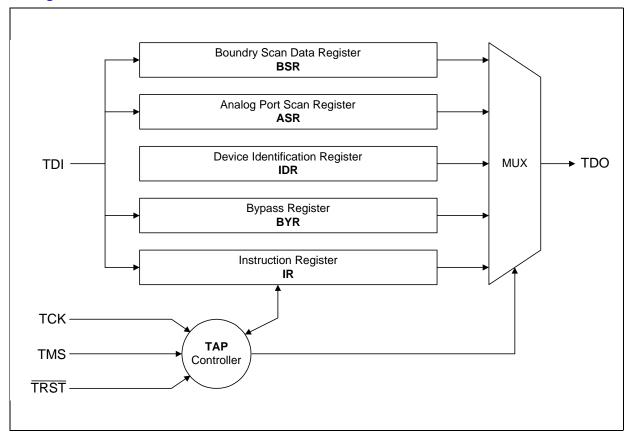
## 4.2 Architecture

The basic JTAG architecture of the LXT384 is illustrated in Figure 15.

The LXT384 JTAG architecture includes a TAP Test Access Port Controller, data registers and an instruction register. The following paragraphs describe these blocks in detail.



Figure 15. JTAG Architecture



# 4.3 TAP Controller

The TAP controller is a 16 state synchronous state machine controlled by the TMS input and clocked by TCK (see Figure 16). The TAP controls whether the LXT384 is in reset mode, receiving an instruction, receiving data, transmitting data or in an idle state. Table 30 describes in detail each of the states represented in Figure 16.

Table 30. TAP State Description (Sheet 1 of 2)

State	Description
Test Logic Reset	In this state the test logic is disabled. The device is set to normal operation mode. While in this state, the instruction register is set to the ICODE instruction.
Run -Test / Idle	The TAP controller stays in this state as long as TMS is Low. Used to perform tests.
Capture - DR	The Boundary Scan Data Register (BSR) is loaded with input pin data.
Shift - DR	Shifts the selected test data registers by one stage tword its serial output.
Update - DR	Data is latched into the parallel output of the BSR when selected.
Capture - IR	Used to load the instruction register with a fixed instruction.
Shift - IR	Shifts the instruction register by one stage.

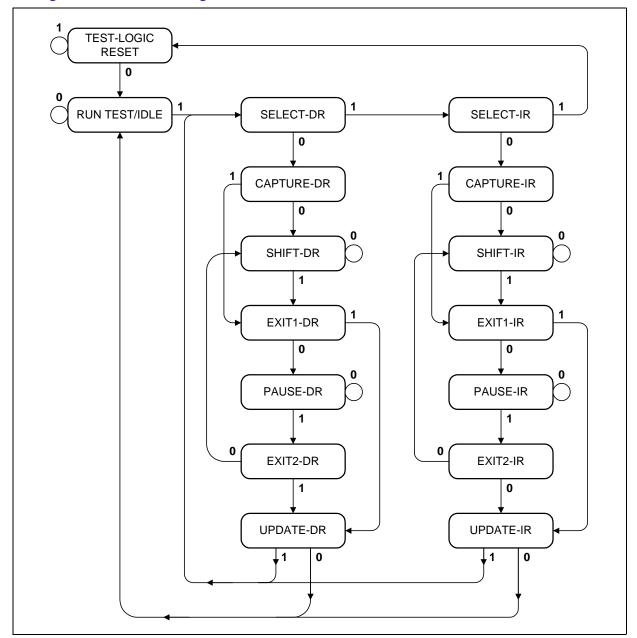


# Table 30. TAP State Description (Sheet 2 of 2)

State	Description			
Update - IR	Loads a new instruction into the instruction register.			
Pause - IR Pause - DR	Momentarily pauses shifting of data through the data/instruction registers.			
Exit1 - IR Exit1 - DR Exit2 - IR Exit2 - DR	Temporary states that can be used to terminate the scanning process.			



Figure 16. JTAG State Diagram



# 4.4 JTAG Register Description

The following paragraphs describe each of the registers represented in Figure 15.



# 4.4.1 Boundary Scan Register (BSR)

The BSR is a shift register that provides access to all the digital I/O pins. The BSR is used to apply and read test patterns to/from the board. Each pin is associated with a scan cell in the BSR register. Bidirectional pins or tristatable pins require more than one position in the register. Table 31 shows the BSR scan cells and their functions. Data into the BSR is shifted in LSB first.

The Analog Test Port can be used to verify continuity across the coupling transformer's primary winding as shown in Figure 17. By applying a stimulus to the AT1 input, a known voltage will appear at AT2 for a given load. This, in effect, tests the continuity of a receive or transmit interface.

Table 31. Boundary Scan Register (BSR) (Sheet 1 of 4)

Bit #	Pin Signal	I/O Type	Bit Symbol	Comments	
0	LOOP0	I/O	PADD0		
1	LOOP0	I/O	PDO0		
2	LOOP1	I/O	PADD1		
3	LOOP1	I/O	PDO1		
4	LOOP2	I/O	PADD2		
5	LOOP2	I/O	PDO2		
6	LOOP3	I/O	PADD3		
7	LOOP3	I/O	PDO3		
8	LOOP4	I/O	PADD4		
9	LOOP4	I/O	PDO4		
10	LOOP5	I/O	PADD5		
11	LOOP5	I/O	PDO5		
12	LOOP6	I/O	PADD6		
13	LOOP6	I/O	PDO6		
14	LOOP7	I/O	PADD7		
15	N/A	-	PDOENB	PDOENB controls the LOOP0 through LOOP7 pins.  Setting PDOENB to "0" configures the pins as outputs. The output value to the pin is set in PDO[07].  Setting PDOENB to "1" tristates all the pins. The input value to the pins can be read in PADD[07].	
16	LOOP7	I/O	PDO7		
17	TCLK1	I	TCLK1		
18	TPOS1	I	TPOS1		
19	TNEG1	I	TNEG1		
20	RCLK1	0	RCLK1		
21	RPOS1	0	RPOS1		
22	N/A	-	HIZ1	HIZ1 controls the RPOS1, RNEG1 and RCLK1 pins. Setting HIZ1 to "0" enables output on the pins. Setting HIZ1 to "1" tristates the pins.	
23	RNEG1	0	RNEG1		
24	LOS1	0	LOS1		



Table 31. Boundary Scan Register (BSR) (Sheet 2 of 4)

Bit #	Pin Signal	I/O Type	Bit Symbol	Comments		
25	TCLK0	I	TCLK0			
26	TPOS0	I	TPOS0			
27	TNEG0	I	TNEG0			
28	RCLK0	0	RCLK0			
29	RPOS0	0	RPOS0			
30	N/A	-	HIZ0	HIZ0 controls the RPOS0, RNEG0 and RCLK0 pins. Setting HIZ0 to "0" enables output on the pins. Setting HIZ0 to "1" tristates the pins.		
31	RNEG0	0	RNEG0			
32	LOS0	0	LOS0			
33	MUX	I	MUX			
34	LOS3	0	LOS3			
35	RNEG3	0	RNEG3			
36	N/A	-	HIZ3	HIZ3 controls the RPOS3, RNEG3 and RCLK3 pins. Setting HIZ3 to "0" enables output on the pins. Setting HIZ3 to "1" tristates the pins.		
37	RPOS3	0	RPOS3			
38	RCLK3	0	RCLK3			
39	TNEG3	I	TNEG3			
40	TPOS3	I	TPOS3			
41	TCLK3	I	TCLK3			
42	LOS2	0	LOS2			
43	RNEG2	0	RNEG2			
44	N/A	-	HIZ2	HIZ2 controls the RPOS2, RNEG2 and RCLK2 pins. Setting HIZ2 to "0" enables output on the pins. Setting HIZ2 to "1" tristates the pins.		
45	RPOS2	0	RPOS2			
46	RCLK2	0	RCLK2			
47	TNEG2	I	TNEG2			
48	TPOS2	I	TPOS2			
49	TCLK2	I	TCLK2			
50	ĪNT	0	INT			
51	N/A	-	SDOACKENB	SDOACKENB controls the ACK pin. Setting SDOACKEN to "0" enables output on ACK pin. Setting SDOACKEN to "1" tristates the pin.		
52	ACK	0	ACK			
53	DS	I	WRB			
54	R/W	I	RDB			
55	ALE	I	ALE			
56	CS	I	CSB			



Table 31. Boundary Scan Register (BSR) (Sheet 3 of 4)

Bit #	Pin Signal	I/O Type	Bit Symbol	Comments
57	MOT/INTL	I	МОТО	
58	TCLK5	I	TCLK5	
59	TPOS5	I	TPOS5	
60	TNEG5	I	TNEG5	
61	RCLK5	0	RCLK5	
62	RPOS5	0	RPOS5	
63	N/A	-	HIZ5	HIZ5 controls the RPOS5, RNEG5 and RCLK5 pins. Setting HIZ5 to "0" enables output on the pins. Setting HIZ5 to "1" tristates the pins.
64	RNEG5	0	RNEG5	
65	LOS5	0	LOS5	
66	TCLK4	I	TCLK4	
67	TPOS4	I	TPOS4	
68	TNEG4	I	TNEG4	
69	RCLK4	0	RCLK4	
70	RPOS4	0	RPOS4	
71	N/A	-	HIZ4	HIZ4 controls the RPOS4, RNEG4 and RCLK4 pins. Setting HIZ4 to "0" enables output on the pins. Setting HIZ4 to "1" tristates the pins.
72	RNEG4	0	RNEG4	
73	LOS4	0	LOS4	
74	OE	I	OE	
75	CLKE	I	CLKE	
76	LOS7	0	LOS7	
77	RNEG7	0	RNEG7	
78	N/A	-	HIZ7	HIZ7 controls the RPOS7, RNEG7 and RCLK7 pins. Setting HIZ7 to "0" enables output on the pins. Setting HIZ7 to "1" tristates the pins.
79	RPOS7	0	RPOS7	
80	RCLK7	0	RCLK7	
81	TNEG7	I	TNEG7	
82	TPOS7	I	TPOS7	
83	TCLK7	I	TCLK7	
84	LOS6	0	LOS6	
85	RNEG6	0	RNEG6	
86	N/A	-	HIZ6	HIZ6 controls the RPOS6, RNEG6 and RCLK6 pins. Setting HIZ6 to "0" enables output on the pins. Setting HIZ6 to "1" tristates the pins.
87	RPOS6	0	RPOS6	
88	RCLK6	0	RCLK6	



Table 31. Boundary Scan Register (BSR) (Sheet 4 of 4)

Bit #	Pin Signal	I/O Type	Bit Symbol	Comments
89	TNEG6	I	TNEG6	
90	TPOS6	I	TPOS6	
91	TCLK6	I	TCLK6	
92	MCLK	I	MCLK	
93	MODE	I	MODE	
94	A4	I	A4	
95	А3	I	А3	
96	A2	I	A2	
97	A1	I	A1	
98	A0	I	A0	

# 4.4.2 Analog Port Scan Register (ASR)

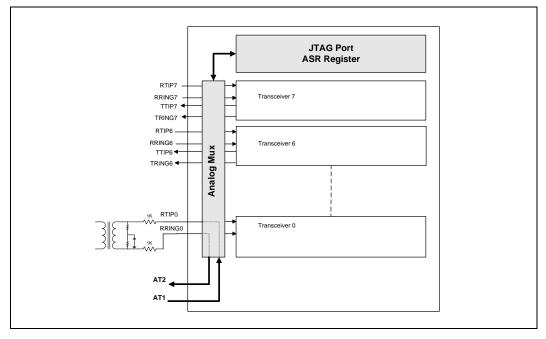
The ASR is a 5 bit shift register used to control the analog test port at pins AT1, AT2. When the INTEST\_ANALOG instruction is selected, TDI connects to the ASR input and TDO connects to the ASR output. After 5 TCK rising edges, a 5 bit control code is loaded into the ASR. Data into the ASR is shifted in LSB first.

Table 32 shows the 16 possible control codes and the corresponding operation on the analog port.

Table 32. Analog Port Scan Register (ASR)

ASR Control Code	AT1 Forces Voltage To:	AT2 Senses Voltage From:
11111	TTIP0	TRING0
11110	TTIP1	TRING1
11101	TTIP2	TRING2
11100	TTIP3	TRING3
11011	TTIP4	TRING4
11010	TTIP5	TRING5
11001	TTIP6	TRING6
11000	TTIP7	TRING7
10111	RTIP0	RRING0
10110	RTIP1	RRING1
10101	RTIP2	RRING2
10100	RTIP3	RRING3
10011	RTIP4	RRING4
10010	RTIP5	RRING5
10001	RTIP6	RRING6
10000	RTIP7	RRING7





**Figure 17. Analog Test Port Application** 

# 4.4.3 Device Identification Register (IDR)

The IDR register provides access to the manufacturer number, part number and the LXT384 revision. The register is arranged per IEEE 1149.1 and is represented in Table 33. Data into the IDR is shifted in LSB first.

Table 33. Device Identification Register (IDR)

Bit #	Comments
31 - 28	Revision number
27 - 12	Part number
11 - 1	Manufacturer number
0	Set to "1"

# 4.4.4 Bypass Register (BYR)

The Bypass Register is a 1 bit register that allows direct connection between the TDI input and the TDO output.

# 4.4.5 Instruction Register (IR)

The IR is a 3 bit shift register that loads the instruction to be performed. The instructions are shifted LSB first. Table 34 shows the valid instruction codes and the corresponding instruction description.



Table 34. Instruction Register (IR)

Instruction	Code #	Comments	
EXTEST	000	Connects the BSR to TDI and TDO. Input pins values are loaded into the BSR. Output pins values are loaded from the BSR.	
INTEST_ANALOG	010	Connects the ASR to TDI and TDO. Allows voltage forcing/sensing through AT1 and AT2. Refer to Table 32.	
SAMPLE / PRELOAD	100	Connects the BSR to TDI and TDO. The normal path between the LXT384 logic and the I/O pins is maintained. The BSR is loaded with the signals in the I/O pins.	
IDCODE	110	Connects the IDR to the TDO pin.	
BYPASS	111	Serial data from the TDI input is passed to the TDO output through the 1 bit Bypass Register.	

# 5.0 Test Specifications

**Note:** Table 35 through Table 54 and Figure 18 through Figure 35 represent the performance specifications of the LXT384 and are guaranteed by test except, where noted, by design. The minimum and maximum values listed in Table 37 through Table 54 are guaranteed over the recommended operating conditions specified in Table 36.

**Table 35. Absolute Maximum Ratings** 

Parameter	Symbol	Min.	Max	Unit
DC supply voltage	Vcc0, Vcc1, Vccio0, Vccio1	-0.5	4.0	V
DC supply voltage	Tvcc 0-7	-0.5	7.0	V
Input voltage on any digital pin	Vin	GND-0.5	5.5	V
Input voltage on RTIP, RRING <sup>1</sup>	Vin	GND-0.5	Vcc0 + 0.5 Vcc1 + 0.5	V
ESD voltage on any Pin <sup>2</sup>	Vin	2000	_	V
Transient latch-up current on any pin	lin		100	mA
Input current on any digital pin 3	lin	-10	10	mA
DC input current on TTIP, TRING <sup>3</sup>	lin	_	±100	mA
DC input current on RTIP, RRING <sup>3</sup>	lin	_	±100	mA
Storage temperature	Tstor	-65	+150	°C
Maximum power dissipation in package	P <sub>P</sub>		1.6	W
Case Temperature, 144 pin LQFP package	T <sub>case</sub>		120	°C
Case Temperature, 160 pin PBGA package	T <sub>case</sub>		120	°C

Caution: Exceeding these values may cause permanent damage. Functional operation under these conditions is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

- 1. Referenced to ground.
- 2. Human body model.
- 3. Constant input current.



**Table 36. Recommended Operating Conditions** 

	Parameter		LEN	Sym	Min.	Тур	Max	Unit	Test Condition		
Digital supp	ply voltage (VCC	and VCCIO)	-	VCC	3.135	3.3	3.465	V	3.3V ± 5%		
Transmitte nominal	Transmitter supply voltage, TVCC=5V nominal			TVCC	4.75	5.0	5.25	V	5V ± 5%		
Transmitte nominal	Transmitter supply voltage, TVCC=3.3V nominal			TVCC	3.135	3.3	3.465	V	3.3V ± 5%		
Ambient op	perating tempera	nture	-	Та	-40	25	+85	°C			
Average tra	ansmitter power	supply current,		I <sub>TVCC</sub>	-	440 230	490 -	mA mA	100% 1's density 50% 1's density		
Average di supply curr	gital power ent <sup>1, 3</sup>			I <sub>VCC</sub>	-	90	120	mA			
Output load TRING	d at TTIP and			RI	25	_		Ω			
		De	evice Pow	er Cons	umption	l					
Mode	TVCC	Load	LEN			Тур	Max <sup>1</sup>	Unit	<b>Test Conditions</b>		
Mode	TVCC			-	-	<b>Typ</b> 760	Max <sup>1</sup>	<b>Unit</b> mW	Test Conditions 50% 1's		
		<b>Load</b> 75 Ω	000	-	-		- 1420				
Mode E1	3.3V	75 Ω	000			760	-	mW	50% 1's		
				-		760 1270	1420	mW mW	50% 1's 100% 1's		
E1	3.3V	75 Ω 120 Ω	000	-	-	760 1270 640	- 1420 -	mW mW mW	50% 1's 100% 1's 50% 1's		
		75 Ω	000	-	-	760 1270 640 1110	- 1420 -	mW mW mW	50% 1's 100% 1's 50% 1's 100% 1's		
E1	3.3V	75 Ω 120 Ω 100 Ω	000 000 101-111		-	760 1270 640 1110 1020	- 1420 - 1280	mW mW mW mW	50% 1's 100% 1's 50% 1's 100% 1's 50% 1's		
E1	3.3V 3.3V	75 Ω 120 Ω	000			760 1270 640 1110 1020 1820	- 1420 - 1280	mW mW mW mW	50% 1's 100% 1's 50% 1's 100% 1's 100% 1's 100% 1's		
E1	3.3V	75 Ω 120 Ω 100 Ω 75 Ω	000 000 101-111 000	- - - -		760 1270 640 1110 1020 1820 1000	- 1420 - 1280 - 2100	mW mW mW mW mW	50% 1's 100% 1's 50% 1's 100% 1's 100% 1's 50% 1's 50% 1's		
E1	3.3V 3.3V	75 Ω 120 Ω 100 Ω	000 000 101-111	- - - - -		760 1270 640 1110 1020 1820 1000 1730	- 1420 - 1280 - 2100 - 1940	mW mW mW mW mW	50% 1's 100% 1's 50% 1's 100% 1's 100% 1's 50% 1's 100% 1's 100% 1's		
E1	3.3V 3.3V	75 Ω 120 Ω 100 Ω 75 Ω	000 000 101-111 000		- - - - -	760 1270 640 1110 1020 1820 1000 1730 820	- 1420 - 1280 - 2100 - 1940	mW mW mW mW mW mW	50% 1's 100% 1's 50% 1's 100% 1's 100% 1's 50% 1's 100% 1's 50% 1's 50% 1's		

Current consumption over the full operating temperature and power supply voltage range. Includes all channels.

Table 37. DC Characteristics (Sheet 1 of 2)

Parameter	Sym	Min.	Тур	Max	Unit	Test Condition
High level input voltage	ViH	2	_	_	V	
Low level input voltage	VIL	_	_	0.8	V	
High level output voltage <sup>1</sup>	Vон	2.4	_	VCCIO	V	IOUT= 400μA
Low level output voltage <sup>1</sup>	Vol	_	_	0.4	V	IOUT= 1.6mA
1. Output drivers will output CMOS	S logic lev	els into CMOS	loads.			

<sup>2.</sup> T1 maximum values measured with maximum cable length (LEN = 111). Typical values measured with typical cable length (LEN = 101).

<sup>3.</sup> Digital inputs are within 10% of the supply rails and digital outputs are driving a 50pF load.



Table 37. DC Characteristics (Sheet 2 of 2)

F	Parameter	Sym	Min.	Тур	Max	Unit	Test Condition
	Low level input voltage	Vinl	-	_	1/3VCC-0.2	V	
MODE,	Midrange level input voltage	Vinm	1/3VCC+0.2	1/2VCC	2/3VCC-0.2	V	
LOOP0-7 and	High level input voltage	Vinh	2/3VCC+0.2	_	-	٧	The VCC supply refers to VCC0 or VCC1 only.
JASEL	Low level input current	linl	-	_	50	μA	
	High level input current	linh	-	_	50	μA	
Input leakage	current	lil	-10		+10	μA	
Tri state leak	age current	lhz	-10		+10	μA	
Tri state outp	ut current	lhz	_	_	1	μA	TTIP, TRING
Line short cir	cuit current	-	-	-	50	mA RMS	2 x 11 Ω series resistors and 1:2 transformer
Input leakage	9	TMS TDI TRST	-	-	50	μA	
1. Output dr	ivers will output CMOS	logic lev	els into CMOS	loads.		I	1

Table 38. E1 Transmit Transmission Characteristics (Sheet 1 of 2)

Pa	arameter	Sym	Min.	Тур	Max	Unit	Test Condition
Output pulse amplitude	se $75\Omega$ $120\Omega$		2.14 2.7	2.37 3.0	2.60 3.3	V V	Tested at the line side
Peak voltage of a space $75\Omega$ $120\Omega$		_	-0.237 -0.3		0.237 0.3	V V	
Transmit amplitude	variation with supply	-	-1		+1	%	
Difference between	pulse sequences	_			200	mV	For 17 consecutive pulses
Pulse width ratio of pulses	the positive and negative	_	0.95		1.05		At the nominal half amplitude
Transmit transforme 75/120Ω characteri		-		1:2			$Rt = 11 \Omega \pm 1\%$
Transmit return	51kHz to 102 kHz		15	17		dB	Using components in
loss 75 Ω coaxial	102 kHz to 2.048 MHz	_	15	17	_	dB	the LXD384
cable <sup>1</sup>	2.048 MHz to 3.072 MHz		15	17		dB	evaluation board.
Transmit return	51kHz to 102 kHz		15	20		dB	Using components in
loss 120 Ω twisted	102 kHz to 2.048 MHz	_	15	20	-	dB	the LXD384
pair cable <sup>1</sup>	2.048 MHz to 3.072 MHz		15	20		dB	evaluation board
1. Guaranteed by	design and other correlatior	metho	ds.		<u> </u>		·



Table 38. E1 Transmit Transmission Characteristics (Sheet 2 of 2)

Parameter			Min.	Тур	Max	Unit	Test Condition
Transmit intrinsic jitter; 20Hz to 100kHz			-	0.030	0.050	U.I.	Tx path TCLK is jitter free
Transmit path	Bipolar mode			2		U.I.	JA Disabled
delay Unipolar mode				7		U.I.	JA Disabled
1. Guaranteed b	y design and other correlation	n metho	ds.				

**Table 39. E1 Receive Transmission Characteristics** 

	Parameter	Sym	Min.	Тур	Max	Unit	Test Condition
Permissible of	Permissible cable attenuation  Receiver dynamic range		-	-	12	dB	@1024 kHz
Receiver dyn	amic range	DR	0.5	-	-	Vp	
Signal to nois	se interference margin	S/I	-15	-	-	dB	Per G.703, O.151 @ 6 dB cable Attenuation
Data decision	Data decision threshold		43	50	57	%	Rel. to peak input voltage
Data slicer th	reshold	_	-	150	_	mV	
Loss of signa	l threshold	_	_	200	_	mV	
LOS hysteres	sis	_	-	50	_	mV	
Consecutive	zeros before loss of signal	-	-	32 2048	I	-	G.775 recommendation ETSI 300 233 specification
LOS reset		_	12.5%	-	_	_	1's density
Low limit input jitter tolerance 1	1Hz to 20Hz 20Hz to 2.4kHz 18kHz to 100kHz	_	36 1.5 0.2	-	-	U.I. U.I. U.I.	G735 recommendation Note 1 Cable Attenuation is 6 dB
Differential re	ceiver input impedance	_	_	70	-	kΩ	@1.024 MHz
Input termina	tion resistor tolerance	_	-	_	±1	%	
Common mo	de input impedance to ground	_	_	20	-	kΩ	
Input return loss <sup>1</sup>	51 kHz - 102 kHz 102 - 2048 kHz 2048kHz - 3072 kHz	-	20 20 20		-	dB dB dB	Measured against nominal impedance using components in the LXD384 evaluation board.
LOS delay tin	ne	-	-	30	-	μs	Data recovery mode
LOS reset		-	10	-	255	marks	Data recovery mode
Receive intrin	sic jitter, RCLK output	-	-	0.040	0.0625	U.I.	Wide band jitter
Receive	Bipolar mode			1		U.I.	JA Disabled
path delay	Unipolar mode			6		U.I.	UA DISANIEU
1. Guarantee	ed by design and other correlat	ion met	thods.				



**Table 40. T1 Transmit Transmission Characteristics** 

Pa	arameter	Sym	Min.	Тур	Max	Unit	Test Condition
Output pulse amplit	tude	_	2.4	3.0	3.6	V	Measured at the DSX
Peak voltage of a s	pace	_	-0.15	-	+0.15	V	
Driver output imped	dance <sup>1</sup>	_	_	1	_	Ω	@ 772 KHz
Transmit amplitude supply	variation with power	_	-1	-	+1	%	
Ratio of positive to	negative pulse amplitude	_	0.95	_	1.05	-	T1.102, isolated pulse
Difference between	pulse sequences	_	_	_	200	mV	For 17 consecutive
Pulse width variation	on at half amplitude	_	_	_	20	ns	pulses, GR-499-CORE
Jitter added by Transmitter <sup>1</sup>	10Hz - 8KHz 8KHz - 40KHz 10Hz - 40KHz Wide Band	-	-	-	0.020 0.025 0.025 0.050	UI <sub>pk-pk</sub>	AT&T Pub 62411 TCLK is jitter free
Output power levels <sup>2</sup>	@ 772 KHz @ 1544 KHz	-	12.6 -29	-	17.9	dBm dBm	T1.102 - 1993 Referenced to power at 772 KHz
Transmit Return Loss <sup>1</sup>	51kHz to 102 kHz 102 kHz to 2.048 MHz 2.048 MHz to 3.072 MHz	_	15 15 15	21 21 21	_	dB dB dB	With transmit series resistors (TVCC=5V). Using components in the LXD384 evaluation board.
Transmit path delay	Bipolar mode Unipolar mode			2 7		U.I.	JA Disabled

Table 41. T1 Receive Transmission Characteristics (Sheet 1 of 2)

Parameter	Sym	Min.	Тур	Max	Unit	Test Condition
Permissible cable attenuation	_	_	_	12	dB	@ 772 KHz
Receiver dynamic range	DR	0.5	_	-	Vp	
Signal to noise interference margin	S/I	-16.5	-	-	dB	@ 655 ft. of 22 ABAM cable
Data decision threshold	SRE	63	70	77	%	Rel. to peak input voltage
Data slicer threshold	_	-	150	-	mV	
Loss of signal threshold	_	_	200	-	mV	
LOS hysteresis	_	_	50	-	mV	
Consecutive zeros before loss of signal	_	100	175	250	-	T1.231 - 1993
LOS reset	_	12.5%	_	-	_	1's density
1. Guaranteed by design and other correla	tion me	thods.				

Guaranteed by design and other correlation methods.
 Power measured in a 3 KHz bandwidth at the point the signal arrives at the distribution frame for an all 1's pattern.



Table 41. T1 Receive Transmission Characteristics (Sheet 2 of 2)

	Parameter	Sym	Min.	Тур	Max	Unit	Test Condition
Low limit input jitter tolerance <sup>1</sup>	0.1Hz to 1Hz 4.9Hz to 300Hz 10KHz to 100KHz	-	138 28 0.4	-	-	U.I. U.I. U.I.	AT&T Pub. 62411
Differential re	ceiver input impedance	-	-	70	-	kΩ	@772 kHz
Input termina	tion resistor tolerance	-	-		±1	%	
Common mod	de input impedance to ground	-	-	20	-	kΩ	
Input return loss <sup>1</sup>	51 KHz - 102 KHz 102 - 2048 KHz 2048 KHz - 3072 KHz	1	20 20 20	-	-	dB dB dB	Measured against nominal impedance. Using components in the LXD384 evaluation board.
LOS delay tin	ne	-	-	30	-	μs	Data recovery mode
LOS reset		-	10	-	255	-	Data recovery mode
Receive intrin	nsic jitter, RCLK output <sup>1</sup>	-	-	0.035	0.0625	U.I.	Wide band jitter
Receive	Bipolar mode			1		U.I.	JA Disabled
path delay	Unipolar mode			6		U.I.	T DISADIEU
1. Guarantee	ed by design and other correlate	ion me	thods.				

Table 42. Jitter Attenuator Characteristics (Sheet 1 of 2)

Parameter			Min.	Тур	Max	Unit	Test Condition
	JACF=0	32bit FIFO	-	2.5	-	Hz	
E1 jitter attenuator 3dB corner frequency, host	3/101 =0	64bit FIFO	-	3.5	-	Hz	
mode <sup>1</sup>	JACF=1	32bit FIFO	ı	2.5	-	Hz	
	3A01 = 1	64bit FIFO	1	3.5	-	Hz	
	JACF=0	32bit FIFO	ı	3	-	Hz	Sinusoidal jitter modulation
T1 jitter attenuator 3dB corner frequency, host	JACI =0	64bit FIFO	ı	3	-	Hz	
mode <sup>1</sup>	JACF=1	32bit FIFO	1	6	-	Hz	
	0A01 = 1	64bit FIFO	-	6	-	Hz	
Jitter attenuator 3dB corner f	requency,	E1	-	3.5	-	Hz	
hardware mode <sup>1</sup>		T1	-	6	-	Hz	
Data latency delay		32bit FIFO	-	16	-	UI	Delay through the Jitter attenuator only. Add receive and
		64bit FIFO	-	32	-	UI	transmit path delay for total throughput delay.
1. Guaranteed by design ar	nd other co	rrelatio	n metho	ds.			



Table 42. Jitter Attenuator Characteristics (Sheet 2 of 2)

Para	meter		Min.	Тур	Max	Unit	Test Condition
Input jitter tolerance before FIFO			-	24	-	UI	
overflow or underflow		64bit FIFO	-	56	-	UI	
E1 jitter attenuation	@ 3 Hz @ 40 Hz @ 400 Hz @ 100 KHz		-0.5 -0.5 +19.5 +19.5	-	-	dB	ITU-T G.736, See Figure 34 on page 75
T1 jitter attenuation	@ 1 Hz @ 20 Hz @ 1 KHz @ 1.4 KHz @ 70 KHz		0 0 33.3 40 40	-	-	dB	AT&T Pub. 62411, See Figure 34 on page 75
Output Jitter in remote	loopback <sup>1</sup>			0.060	0.11	UI	ETSI CTR12/13 Output jitter
1. Guaranteed by des	sign and other co	rrelatio	n metho	ds.			

# **Table 43. Analog Test Port Characteristics**

Parameter	Sym	Min.	Тур	Max	Unit	Test Condition
3 dB bandwidth	At13db	-	5	-	MHz	
Input voltage range	At1iv	0	-	VCC0 VCC1	٧	
Output voltage range	At2ov	0	-	VCC0 VCC1	V	

# Table 44. Transmit Timing Characteristics (Sheet 1 of 2)

Parameter		Sym	Min.	Тур	Max	Unit	Test Condition
Master clock frequency	E1	MCLK	_	2.048	_	MHz	
Master Clock frequency	T1	MCLK	_	1.544	_	MHz	
Master clock tolerance		-	-100	_	100	ppm	
Master clock duty cycle		-	40	_	60	%	
Output pulse width	E1	Tw	219	244	269	ns	
Output puise width	T1	Tw	291	324	356	ns	
Transmit clock frequency	E1	Tclke1	-	2.048	-	MHz	
Transmit clock frequency	T1	Tclkt1	-	1.544	-	MHz	
Transmit clock tolerance		Tclkt	-50	-	+50	ppm	
Transmit clock burst rate		Tclkb	-	_	20	MHz	Gapped transmit clock
Transmit clock duty cycle		Tdc	10	-	90	%	NRZ mode
E1 TPOS/TNEG pulse width (RZ mode)		Tmpwe1	236	-	252	ns	RZ mode (TCLK = H for >16 clock cycles)
TPOS/TNEG to TCLK setup time		Tsut	20	-	-	ns	



Table 44. Transmit Timing Characteristics (Sheet 2 of 2)

Parameter	Sym	Min.	Тур	Max	Unit	Test Condition
TCLK to TPOS/TNEG hold time	Tht	20	-	-	ns	
Delay time OE Low to driver High Z	Toez	-	-	1	μs	
Delay time TCLK Low to driver High Z	Ttz	50	60	75	μs	

**Figure 18. Transmit Clock Timing Diagram** 

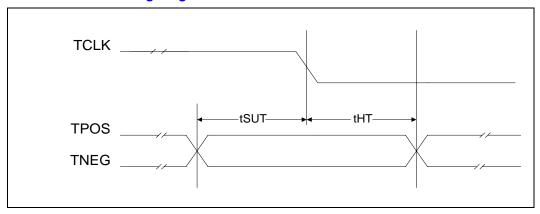


Table 45. Receive Timing Characteristics (Sheet 1 of 2)

Parameter		Sym	Min.	Тур	Max	Unit	Test Condition
0	E1	-	-	±80	_	ppm	Relative to nominal
Clock recovery capture range	T1	_	1	±180	-	ppm	frequency MCLK = ±100 ppm
Receive clock duty cycle <sup>1</sup>		Rckd	40	50	60	%	
Receive clock pulse width <sup>1</sup>	E1	Tpw	447	488	529	ns	
Receive clock pulse width		Tpw	583	648	713	ns	
Receive clock pulse width Low time	E1	Tpwl	203	244	285	ns	
	T1	Tpwl	259	324	389	ns	
Receive clock pulse width High time	E1	Tpwh	203	244	285	ns	
Receive clock pulse width high time	T1	Tpwh	259	324	389	ns	
Rise/fall time <sup>4</sup>		Tr	20	-	-	ns	@ CL=15 pF
RPOS/RNEG pulse width (MCLK=H) <sup>2</sup>	E1	Tpwdl	200	244	300	ns	
KFOS/KINEG puise width (MCLK=II)	T1	Tpwdl	250	324	400	ns	
RPOS/RNEG to RCLK rising setup time	E1	Tsur	200	244	-	ns	
	T1	isui	200	324	_	ns	
4 DOLK 1 4 1 1 1 1 1 1 1							

RCLK duty cycle widths will vary depending on extent of received pulse jitter displacement. Maximum and minimum RCLK duty cycles are for worst case jitter conditions (0.2UI displacement for E1 per ITU G.823).

<sup>2.</sup> Clock recovery is disabled in this mode.

<sup>3.</sup> If MCLK = H the receive PLLs are replaced by a simple EXOR circuit.

<sup>4.</sup> For all digital outputs.

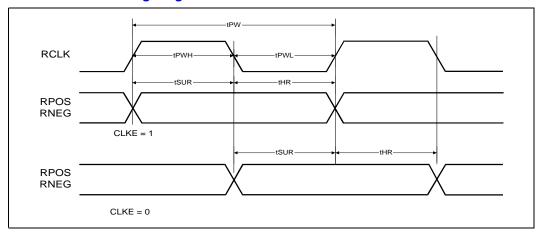


Table 45. Receive Timing Characteristics (Sheet 2 of 2)

Parameter		Sym	Min.	Тур	Max	Unit	Test Condition
RCLK Rising to RPOS/RNEG hold time	E1	Thr	200	244	-	ns	
ROLK KISING to KI OS/KINEO Hold time	T1		200	324	-	ns	
Delay time between RPOS/RNEG and RCLK		-	-	-	5	ns	MCLK = H <sup>3</sup>

- RCLK duty cycle widths will vary depending on extent of received pulse jitter displacement. Maximum and minimum RCLK duty cycles are for worst case jitter conditions (0.2UI displacement for E1 per ITU G.823).
- 2. Clock recovery is disabled in this mode.
- 3. If MCLK = H the receive PLLs are replaced by a simple EXOR circuit.
- 4. For all digital outputs.

Figure 19. Receive Clock Timing Diagram



**Table 46. JTAG Timing Characteristics** 

Parameter	Sym	Min.	Тур	Max	Unit	Test Conditions
Cycle time	Tcyc	200	-	-	ns	
J-TMS/J-TDI to J-TCK rising edge time	Tsut	50	-	-	ns	
J-CLK rising to J-TMS/L-TDI hold time	Tht	50	-	-	ns	
J-TCLK falling to J-TDO valid	Tdod	-	-	50	ns	



Figure 20. JTAG Timing

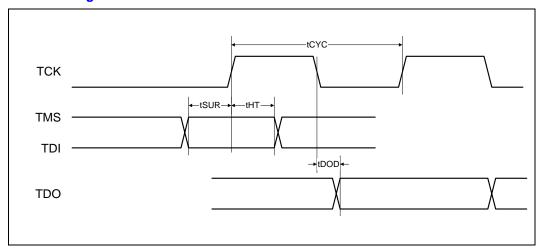


Table 47. Intel Mode Read Timing Characteristics<sup>2</sup>

Parameter	Sym	Min.	Typ <sup>1</sup>	Max	Unit	Test Conditions
Address setup time to latch	Tsalr	10	_	_	ns	
Valid address latch pulse width	TvI	30	_	_	ns	
Latch active to active read setup time	Tslr	10	_	_	ns	
Chip select setup time to active read	Tscsr	0	_	_	ns	
Chip select hold time from inactive read	Thcsr	0	_	_	ns	
Address hold time from inactive ALE	Thalr	5			ns	
Active read to data valid delay time	Tprd	10	_	50	ns	
Address setup time to RD inactive	Thar	1	_	_	ns	
Address hold time from RD inactive	Tsar	5	_	_	ns	
Inactive read to data tri-state delay time	Tzrd	3	_	35	ns	
Valid read signal pulse width	Tvrd	60	-	_	ns	
Inactive read to inactive INT delay time	Tint	_	-	10	ns	
Active chip select to RDY delay time	Tdrdy	0	-	12	ns	
Active ready Low time	Tvrdy	_	_	40	ns	
Inactive ready to tri-state delay time	Trdyz	-	-	3	ns	

<sup>1.</sup> Typical figures are at 25 C and are for design aid only; not guaranteed and not subject to production testing.

2. C<sub>L</sub>= 100pF on D0-D7, all other outputs are loaded with 50pF.



Figure 21. Non-Multiplexed Intel Mode Read Timing

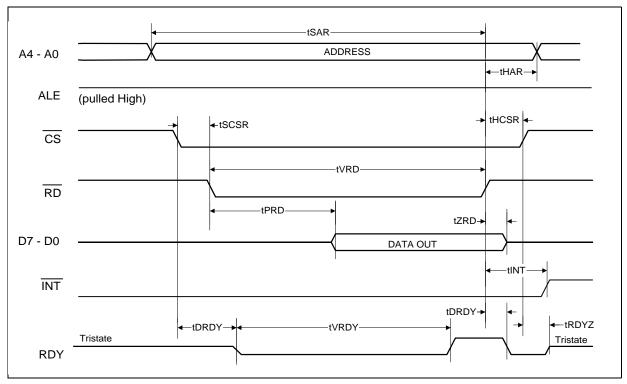


Figure 22. Multiplexed Intel Mode Read Timing

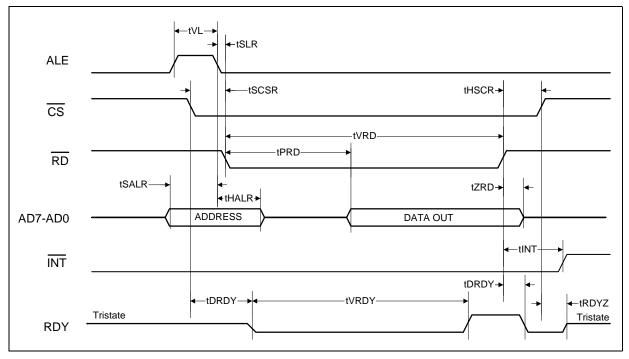




Table 48. Intel Mode Write Timing Characteristics<sup>2</sup>

Parameter	Sym	Min.	Typ <sup>1</sup>	Max	Unit	Test Conditions
Address setup time to latch	Tsalw	10	-	-	ns	
Valid address latch pulse width	TvI	30	_	_	ns	
Latch active to active write setup time	Tslw	10	_	_	ns	
Chip select setup time to active write	Tscsw	0	_	_	ns	
Chip select hold time from inactive write	Thcsw	0	_	_	ns	
Address hold time from inactive ALE	Thalw	5			ns	
Data valid to write active setup time	Tsdw	40	_	_	ns	
Data hold time to active write	Thdw	30	_	_	ns	
Address setup time to WR inactive	Thaw	2	_	_	ns	
Address hold time from WR inactive	Tsaw	6	_	_	ns	
Valid write signal pulse width	Tvwr	60	_	_	ns	
Inactive write to inactive INT delay time	Tint	_	_	10	ns	
Chip select to RDY delay time <sup>3</sup>	Tdrdy	0	_	12	ns	
Active ready Low time	Tvrdy	_	-	40	ns	
Inactive ready to tri-state delay time <sup>3</sup>	Trdyz	_	_	3	ns	

<sup>1.</sup> Typical figures are at 25 C and are for design aid only; not guaranteed and not subject to production testing.

2. C<sub>L</sub>= 100pF on D0-D7, all other outputs are loaded with 50pF.

3. These times don't apply for Reset Register 0Ah, since RDY line goes low once during the cycle. Please

refer to Reset Operation and Host Mode sections for more information.



Figure 23. Non-Multiplexed Intel Mode Write Timing

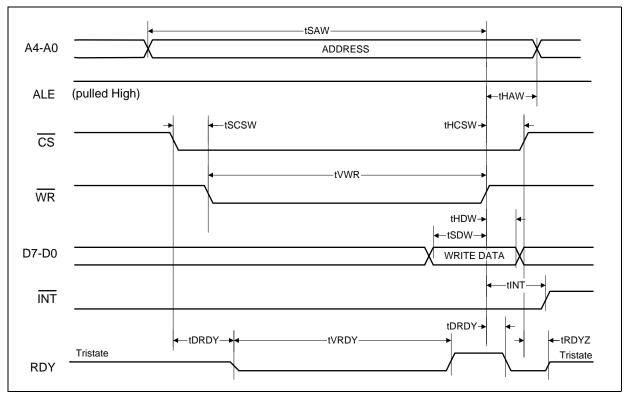


Figure 24. Multiplexed Intel Mode Write Timing

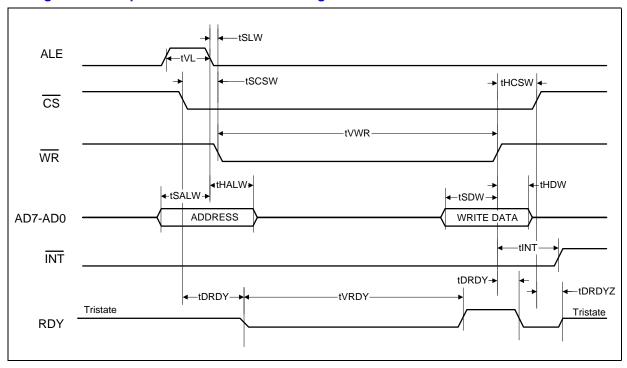




Table 49. Motorola Bus Read Timing Characteristics<sup>2</sup>

Parameter	Sym	Min.	Typ <sup>1</sup>	Max	Unit	Test Conditions
Address setup time to address or data strobe	Tsar	10	_	_	ns	
Address hold time from address or data strobe	Thar	5	_	_	ns	
Valid address strobe pulse width	Tvas	95	_	_	ns	
R/W setup time to active data strobe	Tsrw	10	_	_	ns	
R/W hold time from inactive data strobe	Thrw	0	_	_	ns	
Chip select setup time to active data strobe	Tscs	0	_	_	ns	
Chip select hold time from inactive data strobe	Thcs	0	_	_	ns	
Address strobe active to data strobe active delay	Tasds	20	_	_	ns	
Delay time from active data strobe to valid data	Tpds	3	_	30	ns	
Delay time from inactive data strobe to data High Z	Tdz	3	_	30	ns	
Valid data strobe pulse width	Tvds	60	_	_	ns	
Inactive data strobe to inactive INT delay time	Tint	_	_	10	ns	
Data strobe inactive to address strobe inactive delay	Tdsas	15	_	_	ns	
DS asserted to ACK asserted delay	Tdackp	_	_	40	ns	
DS deasserted to ACK deasserted delay	Tdack	_	_	10	ns	
Active ACK to valid data delay	Tpack	_	_	0	ns	

<sup>1.</sup> Typical figures are at 25 C and are for design aid only; not guaranteed and not subject to production testing.

<sup>2.</sup>  $C_L$ = 100pF on D0-D7, all other outputs are loaded with 50pF.



Figure 25. Non-Multiplexed Motorola Mode Read Timing

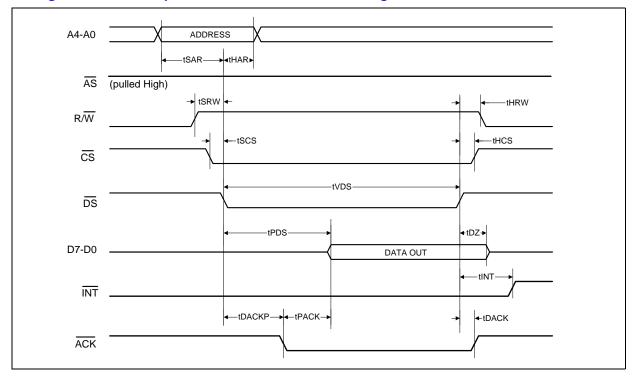


Figure 26. Multiplexed Motorola Mode Read Timing

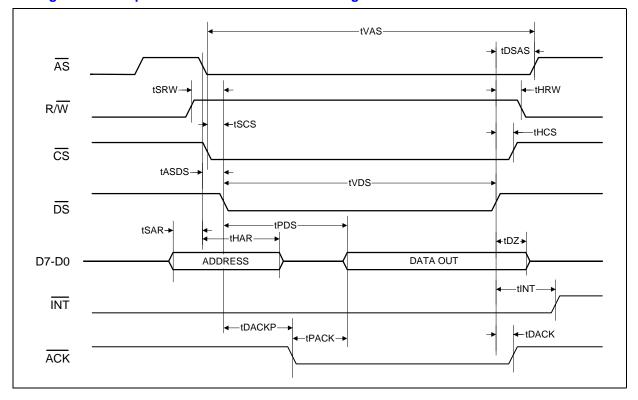




Table 50. Motorola Mode Write Timing Characteristics<sup>2</sup>

Parameter	Sym	Min.	Typ <sup>1</sup>	Max	Unit	<b>Test Conditions</b>
Address setup time to address strobe	Tsas	10	_	_	ns	
Address hold time to address strobe	Thas	5	_	_	ns	
Valid address strobe pulse width	Tvas	95	_	_	ns	
R/W setup time to active data strobe	Tsrw	10	_	_	ns	
R/W hold time from inactive data strobe	Thrw	0	_	_	ns	
Chip select setup time to active data strobe	Tscs	0	_	_	ns	
Chip select hold time from inactive data strobe	Thcs	0	_	_	ns	
Address strobe active to data strobe active delay	Tasds	20	_	_	ns	
Data setup time to DS deassertion	Tsdw	40	_	_	ns	
Data hold time from DS deassertion	Thdw	30	_	_	ns	
Valid data strobe pulse width	Tvds	60	_	_	ns	
Inactive data strobe to inactive INT delay time	Tint	_	_	10	ns	
Data strobe inactive to address strobe inactive delay	Tdsas	15	_	_	ns	
Active data strobe to ACK output enable time	Tdack	0	_	12	ns	
DS asserted to ACK asserted delay	Tdackp		_	40	ns	

<sup>1.</sup> Typical figures are at 25 C and are for design aid only; not guaranteed and not subject to production testing.

2. C<sub>L</sub>= 100pF on D0-D7, all other outputs are loaded with 50pF.

Figure 27. Non-Multiplexed Motorola Mode Write Timing

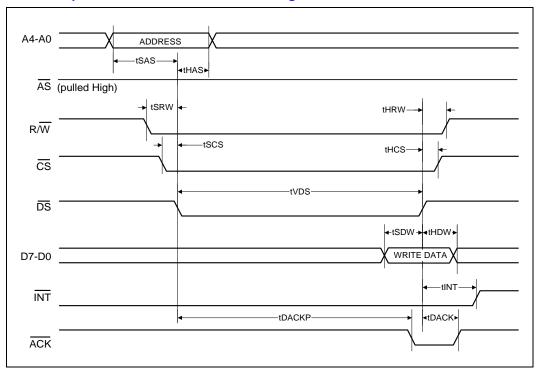




Figure 28. Multiplexed Motorola Mode Write Timing

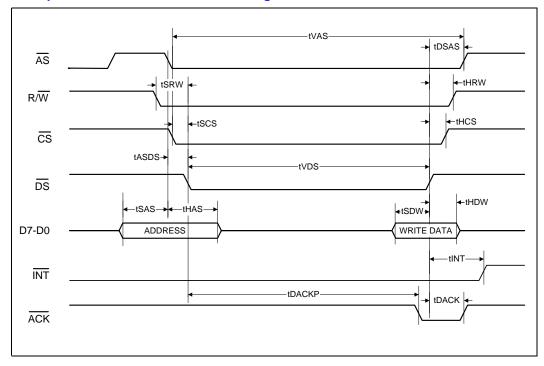


Table 51. Serial I/O Timing Characteristics

Parameter	Sym	Min.	Typ <sup>1</sup>	Max	Unit	Test Condition			
Rise/fall time any pin	Trf	-	-	100	ns	Load 1.6mA, 50 pF			
SDI to SCLK setup time	Tdc	5	-	-	ns				
SCLK to SDI hold time	Tcdh	5	-	-	ns				
SCLK Low time	Tcl	25	-	-	ns				
SCLK High time	Tch	25	-	-	ns				
SCLK rise and fall time	Tr, Tf	-	-	50	ns				
CS falling edge to SCLK rising edge	Tcc	10	-	-	ns				
Last SCLK edge to CS rising edge	Tcch	10	-	-	ns				
CS inactive time	Tcwh	50	-	-	ns				
SCLK to SDO valid delay time	Tcdv	-	-	5	ns				
SCLK falling edge or $\overline{\text{CS}}$ rising edge to SDO High Z	Tcdz	-	10	-	ns				

<sup>1.</sup> Typical figures are at 25 C and are for design aid only; not guaranteed and not subject to production testing.



Figure 29. Serial Input Timing

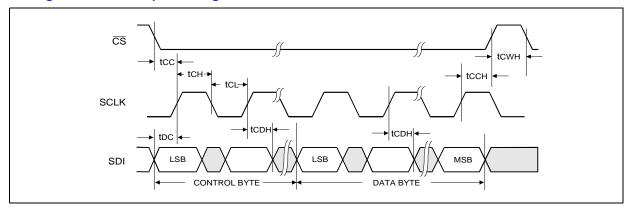
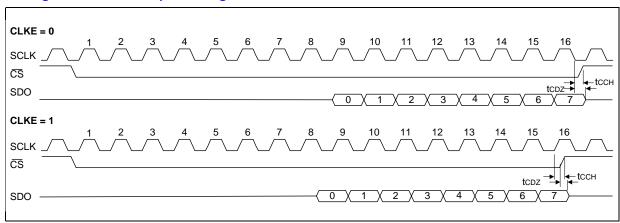


Figure 30. Serial Output Timing



**Table 52. Transformer Specifications** 

Tx/Rx	Turns Ratio <sup>2</sup>	Primary Inductance mH (min.)	Leakage Inductance μH (max.)	Interwinding Capacitance pF (max.)	DCR $\Omega$ (max.)	Dielectric Breakdown Voltage V <sup>1</sup> (min.)
TX	1:2	1.2	0.60	60	0.70 pri 1.20 sec	1500 Vrms
RX	1:2	1.2	0.60	60	1.10 pri 1.10 sec	1500 Vrms

<sup>1.</sup> This parameter is application dependent. 2. LIU side: Line side. Transformer turns ratio accuracy is  $\pm$  2%.



Table 53. G.703 2.048 Mbit/s Pulse Mask Specifications

Parameter	Ca	Unit	
rarameter	TWP	Coax	Onit
Test load impedance	120	75	Ω
Nominal peak mark voltage	3.0	2.37	V
Nominal peak space voltage	0 ±0.30	0 ±0.237	V
Nominal pulse width	244	244	ns
Ratio of positive and negative pulse amplitudes at center of pulse	95-105	95-105	%
Ratio of positive and negative pulse amplitudes at nominal half amplitude	95-105	95-105	%

Figure 31. E1, G.703 Mask Templates

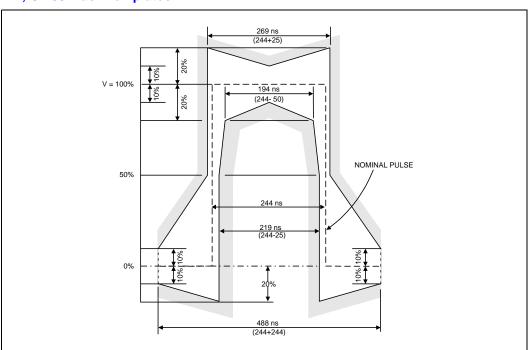
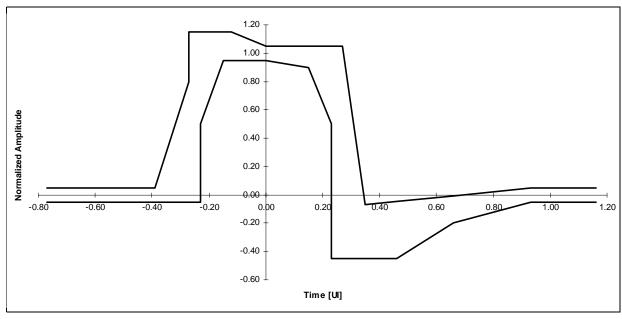


Table 54. T1.102 1.544 Mbit/s Pulse Mask Specifications

Deservator	Cable	Unit
Parameter Parameter	TWP	Unit
Test load impedance	100	Ω
Nominal peak mark voltage	3.0	V
Nominal peak space voltage	0 ±0.15	V
Nominal pulse width	324	ns
Ratio of positive and negative pulse amplitudes	95-105	%











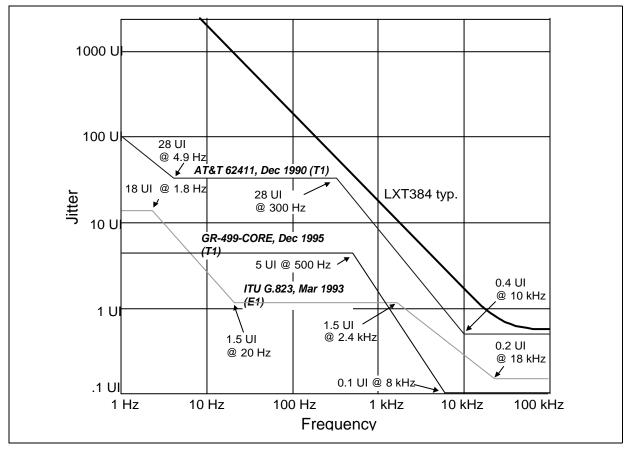
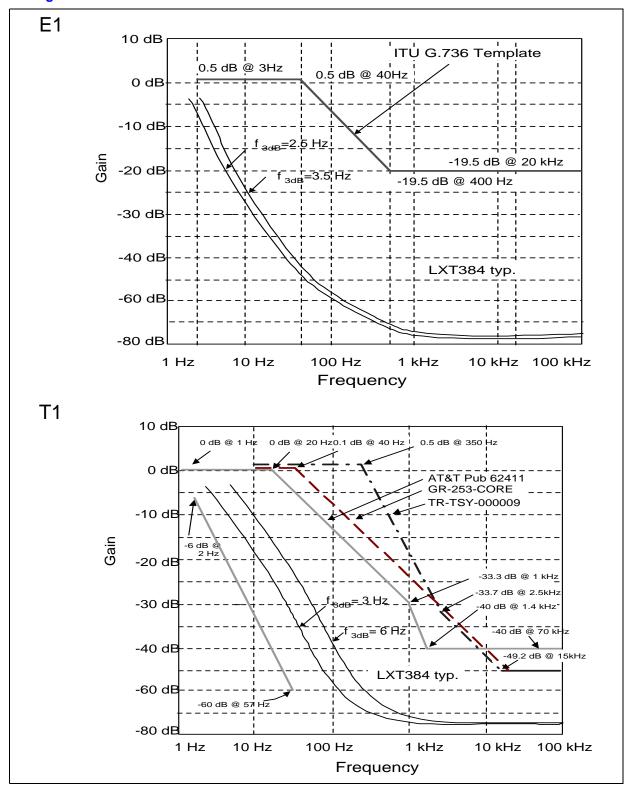




Figure 34. LXT384 Jitter Transfer Performance





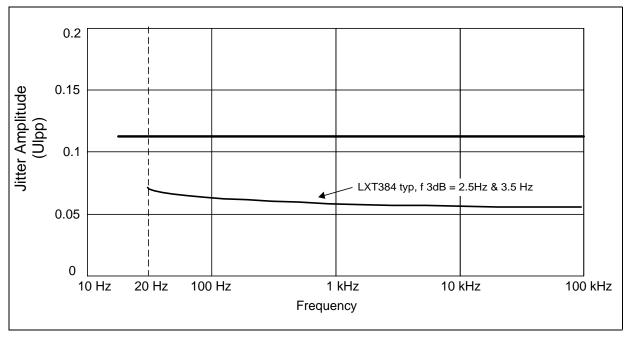


Figure 35. LXT384 Output Jitter for CTR12/13 Applications

# 5.1 Recommendations and Specifications

- AT&T Pub 62411
- ANSI T1.102 199X Digital Hierarchy Electrical Interface
- ANSI T1.231 -1993 Digital Hierarchy Layer 1 In-Service Digital Transmission Performance Monitoring
- Bellcore TR-TSY-000009 Asynchronous Digital Multiplexes Requirements and Objectives
- Bellcore GR-253-CORE SONET Transport Systems Common Generic Criteria
- Bellcore GR-499-CORE Transport Systems Generic Requirements
- ETS 300166 Physical and Electrical Characteristics
- ETS 300386-1 Electromagnetic Compatibility Requirement
- G.703 Physical/electrical characteristics of hierarchical digital interfaces
- G. 704 Functional characteristics of interfaces associated with network nodes
- G.735 Characteristics of Primary PCM multiplex equipment operating at 2048 kbit/s and offering digital access at 384 kbit/s and/or synchronous digital access at 64 kbit/s
- G.736 Characteristics of a synchronous digital multiplex equipment operating at 2048 kbit/s
- G.772 Protected Monitoring Points provided on Digital Transmission Systems
- G.775 Loss Of Signal (LOS) and alarm indication (AIS) defect detection and clearance criteria
- G.783 Characteristics of Synchronous Digital Hierarchy (SDH) Equipment Functional Blocks

## Octal T1/E1/J1 Transceiver — LXT384

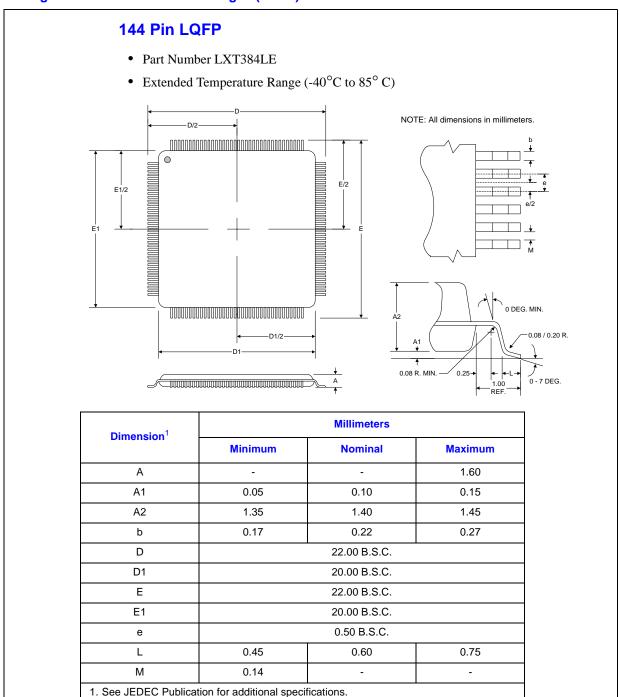


- G.823 The control of jitter and wander within digital networks which are based on the 2048 kbit/s hierarchy
- O.151 Specification of instruments to measure error performance in digital systems
- OFTEL OTR-001 Short Circuit Current Requirements



# 6.0 Mechanical Specifications

Figure 36. Low Quad Flat Packages (LQFP) Dimensions



SPECIFIED OTHERWISE.



160 Pin PBGA • Part Number LXT384BE Extended Temperature Range (-40°C to 85°C) 15.00 13.00 ±0.20 1.00 REF→ -13.00 4.72 ±0.10-PIN #A1-CORNER 1.00→ <del>\_\_</del>000<del>00</del>00|000000 <sub>0.50</sub> B 0000000000000 ►PIN #A1 ID ±0.10 C 0000000000000 D 4.72 ±0.10 Ε 0000 0000 1.00 F 0000 0000 0000 0000 G 13.00 ±0.20 15.00 0000 0000 Н 0000 0000 0000 0000 Κ 0000000000000 0000000000000 М 0000000000000 Ø1.00 14 13 12 11 10 9 8 7 6 5 4 3 2 1 (3 plcs) **TOP VIEW BOTTOM VIEW NOTE:** ± 0.19 0.85 1. ALL DIMENSIONS IN MILLIMETERS. 2. ALL DIMENSIONS AND TOLERANCES 0.56 CONFORM TO ASME Y 14.5M-1994. 0.40 SEATING PLANE 3. TOLERANCE =  $\pm 0.05$  UNLESS ± 0.10

Figure 37. Plastic Ball Grid Array (PBGA) Package Dimensions

SIDE VIEW